

STMICROELECTRONICS NV  
Form 6-K  
June 07, 2010

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UNITED STATES SECURITIES AND EXCHANGE COMMISSION

Washington, D.C. 20549

FORM 6-K

REPORT OF FOREIGN PRIVATE ISSUER  
PURSUANT TO RULE 13a-16 OR 15d-16 UNDER  
THE SECURITIES EXCHANGE ACT OF 1934

Report on Form 6-K dated June 4, 2010

Commission File Number: 1-13546

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STMicroelectronics N.V.  
(Name of Registrant)

39, Chemin du Champ-des-Filles  
1228 Plan-les-Ouates, Geneva, Switzerland

(Address of Principal Executive Offices)

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Indicate by check mark whether the registrant files or will file annual reports under cover of Form 20-F or Form 40-F.

Form 20-F

Form 40-F

Indicate by check mark if the registrant is submitting the Form 6-K in paper as permitted by Regulation S-T Rule 101(b)(1):

Yes

No

Indicate by check mark if the registrant is submitting the Form 6-K in paper as permitted by Regulation S-T Rule 101(b)(7):

Yes

No

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Indicate by check mark whether the registrant by furnishing the information contained in this form is also thereby furnishing the information to the Commission pursuant to Rule 12g3-2(b) under the Securities Exchange Act of 1934.

Yes

No

If "Yes" is marked, indicate below the file number assigned to the registrant in connection with Rule 12g3-2(b): 82-

\_\_\_\_\_

Enclosure: A presentation prepared by STMicroelectronics with respect to its Field Day at its Field Day held in London, England on June 3, 2010.

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Field Trip 2010  
London, June 3

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Welcome & Introduction

Tait Sorensen  
Director - Investor Relations

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Field Trip Agenda

Time Presentation Speaker

10:00 am Welcome & Introduction T. Sorensen

10:05 Company Strategy & Vision C. Bozotti

10:25 ST Business & Operations A. Dutheil

10:45 Financial Performance & Roadmap C. Ferro

11:05 Sustainable Technology & Leadership J-M. Chery

11:25 Q&A Panel C. Bozotti/A. Dutheil/C. Ferro/J-M. Chery

11:50 BREAK

12:00pm Multimedia Convergence & ACCI Sector Overview P. Lambinet

12:20 IMS Overview & Advanced Analog & Smart Power C. Papa

12:40 ST-Ericsson: Towards Transformation G. Delfassy

1:00 Q&A Panel C. Bozotti/P. Lambinet/C. Papa /G. Delfassy

1:30 LUNCH

2:30 Breakout Sessions

5:00 - 6:30 Reception

Field Trip Agenda - Breakout Sessions

Ballroom  
Ground Floor  
Mirror Room  
Ground Floor  
St. James  
6th Floor  
Clarence  
6th Floor  
Boardroom  
6th Floor  
Kensington  
6th Floor  
2:30 - 3:00 ST-Ericsson Home  
Entertainment Automotive MCUs  
3:00 - 3:30 ST-Ericsson Automotive Americas MEMS  
3:30 - 4:00 ST-Ericsson Home  
Entertainment  
Computer &  
Networking MCUs  
4:00 - 4:30 Computer &  
Networking Automotive Americas MEMS  
4:30 - 5:00 Home  
Entertainment  
Computer &  
Networking Americas Power & Smart  
Power  
5:00 Reception - Ballroom Reception Area

- o Americas: The Land of Opportunity (R. Krysiak)
  - o Automotive (P. Grimme)
  - o Computer & Networking (GL Bertino)
  - o Home Entertainment (P. Lambinet)
  - o MCUs (C. Dardanne)
  - o MEMS & Adv. Analog (B. Vigna)
  - o Power & Smart Power (M. Lo Presti)
  - o ST-Ericsson (P. Langlois)
-

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### Forward Looking Statements

- o Some of the statements contained in these presentations that are not historical facts are statements of future expectations and other forward-looking statements (within the meaning of Section 27A of the Securities Act of 1933 or Section 21E of the Securities Exchange Act of 1934, each as amended) that are based on management's current views and assumptions, and are conditioned upon and also involve known and unknown risks and uncertainties that could cause actual results, performance or events to differ materially from those in such statements due to, among other factors:
  - o Significant changes in demand in the key application markets and from key customers served by our products make it extremely difficult to accurately forecast and plan our future business activities. In particular, following a period of significant order cancellations, we recently experienced a strong surge in customer demand, which has led to capacity constraints in certain applications;
  - o our ability to utilize and operate our manufacturing facilities at sufficient levels to cover fixed operating costs in periods of reduced customer demand, as well as our ability to ramp up production efficiently and rapidly to respond to increased customer demand, and the financial impact of obsolete or excess inventories if actual demand differs from our expectations;
  - o our ability to successfully integrate the acquisitions we pursue, in particular the successful integration and operation of the ST-Ericsson joint venture;
  - o ST-Ericsson is a new wireless joint venture, representing a significant investment and risk for our business. The joint venture is currently engaged in restructuring initiatives and further declines in the wireless market, as well as the inability of ST-Ericsson to complete its ongoing restructuring plans or to successfully compete, could result in additional significant impairment and restructuring charges;
  - o we currently hold a significant financial investment in Micron Technology Inc ("Micron") as a result of the previously announced sale to Micron of our equity investment in Numonyx in an all-stock transaction. Our shares in Micron are subject to certain resale restrictions and, consequently, there is no guaranty as to when we will be able to sell them and at what price;
  - o our ability to compete in our industry since a high percentage of our costs are fixed and are incurred in currencies other than U.S. dollars, especially in light of the volatility in the foreign exchange markets and, more particularly, in the U.S. dollar exchange rate as compared to the other major currencies we use for our operations;
  - o the outcome of ongoing litigation as well as any new litigation to which we may become a defendant;
  - o changes in our overall tax position as a result of changes in tax laws or the outcome of tax audits, and our ability to accurately estimate

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tax credits, benefits, deductions and provisions and to realize deferred tax assets;

- o the impact of intellectual property ("IP") claims by our competitors or other third parties, and our ability to obtain required licenses on reasonable terms and conditions;
  - o our ability to execute our restructuring initiatives in accordance with our plans if unforeseen events require adjustments or delays in implementation or require new plans;
  - o our ability in an intensively competitive environment to secure customer acceptance and to achieve our pricing expectations for high volume supplies of new high-products in whose development we have been, or are currently, investing;
  - o changes in the political, social or economic environment, including as a result of military conflict, social unrest and/or terrorist activities, economic turmoil, as well as natural events such as severe weather, health risks, epidemics, earthquakes, volcano eruptions or other acts of nature in, or affecting, the countries in which we, our key customers or our suppliers, operate.
- o Such forward-looking statements are subject to various risks and uncertainties, which may cause actual results and performance of our business to differ materially and adversely from the forward-looking statements. Certain forward-looking statements can be identified by the use of forward-looking terminology, such as "believes," "expects," "may," "are expected to," "should," "would be," "seeks" or "anticipates" or similar expressions or the negative thereof or other variations thereof or comparable terminology, or by discussions of strategy, plans or intentions. Some of these risk factors are set forth and are discussed in more detail in "Item 3. Key Information-- Risk Factors" included in our Annual Report on Form 20-F for the year ended December 31, 2009, as filed with the SEC on March 10, 2010. Should one or more of these risks or uncertainties materialize, or should underlying assumptions prove incorrect, actual results may vary materially from those described in this release as anticipated, believed or expected. We do not intend, and do not assume any obligation, to update any industry information or forward-looking statements set forth in this release to reflect subsequent events or circumstances.
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Company Strategy & Vision  
Carlo Bozotti  
President and Chief Executive Officer

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ST Business & Operations  
Alain Dutheil  
Chief Operating Officer

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A Year-Ago...The Global Recession

- o Semiconductor bookings dropped rapidly in Q408; demand remained weak in first half of 2009
  - o Impact on industry's revenue evolution greater than initially expected
  - o Industry utilization rates reached unprecedented low levels; capacity cut to react to lack of demand
  - o Inventory levels were substantially reduced
  - o Economic impact varied by geography
  - o China - started to recover
  - o Europe, US and Japan - still difficult conditions
  - o Global market bottomed in mid-2009
-

Managed Well Through the Downturn...

- o ST exited the recession a stronger and leaner company
- o Increased operating leverage
- o Completed ~\$750M of cost savings initiatives in 2009
- o Improved financial strength and stability
- o Over \$2.76B in gross cash and marketable securities exiting March 2010
- o Continued progress in advanced technology R&D partnerships
- o Reshaped manufacturing
- o Committed to the ongoing integration of ST-Ericsson
- o Performance of ST's global team
- o Reacted quickly to align manufacturing, costs and working capital to end markets
- o Stayed focused on customers

2009 Semiconductor Industry Revenue

TAM: -9%

SAM: -13%

ST (ex FMG): -10.8%

Today's Priorities

- o Resuming progress towards long-term financial goals
- o Focused on reaching sustainable levels of sales and net income
- o Organic growth / new product innovation
- o Disciplined portfolio management
- o Leveraging global scale and scope
- o Commitment to shareholder value creation
- o ST-Ericsson
- o Competitive cost structure / completion of announced restructuring programs
- o New portfolio
- o Preparing the company for future, profitable growth

Current Expectations

2010 Semiconductor Industry Revenue

SAM: approximately +20%

Semiconductor Industry

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Semiconductor Market Growth  
Total Available Market  
~16% per year ~8% per year  
~13% ex FY2000  
2008-09  
-9%

- o Demand driven cycle less severe
  - o Recession led to 2 years of decline
  - o Semis well positioned to grow in future years
- Source: WSTS

Key Target Areas

Total Available Market

Application Product

Industrial 9%

Automotive 7%

Wired 6%

Wireless 21%

Data Processing 38%

Consumer 19%

Application

Specific ICs

39%

Standard ICs

6%

Discrete

6%

MCU

5%

Other

Memories

2%

Sensors &

Actuators

2%

Non SAM

40%

ST: well positioned, diversified, many opportunities

Source: iSuppli (including memories), WSTS



Market Mega-Trends

- o Multimedia convergence is accelerating
  - o Re-rating of industry growth
  - o Semiconductor market is moving East
  - o Cost of fabs and process R&D are soaring
  - o Foundries are getting a significant share of semi business
  - o R&D is shifting across the value chain
  - o Industry is consolidating by application
  - o Pervasion into new high-growth industries
-

Company Overview

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STMicroelectronics  
A Global Semiconductor Company

Q110 revenue: \$2,325M  
By location of order shipment

13%  
America  
27%  
EMEA  
41%  
Greater  
China &  
South Asia  
19%  
Japan &  
Korea

- o FY09 revenues of \$8.51B
  - o 15 main manufacturing sites
  - o Advanced R&D centers in 10 countries
  - o Over 51,000 employees, including ST-Ericsson
  - o Listed on NYSE Euronext (New York & Paris) and Milan stock exchanges
-

The Evolution of ST

2010  
Completed the sale of Numonyx to Micron  
2009  
ST and Ericsson created ST-Ericsson JV  
2008  
Deconsolidation of Flash, acquired NXP Wireless,  
announced the JV with Ericsson Mobile Platforms  
2005  
New CEO  
2000  
Became #1 European semiconductor company  
1999  
Entered world's Top Ten semiconductor suppliers  
1994  
IPO  
O  
1987  
Merger of SGS Microelettronica of Italy and  
Thomson Semiconducteurs of France

STMicroelectronics Today

5th largest global semiconductor company - #1 in Europe \*  
Focus on multimedia applications, analog and power  
management  
World leading positions in wireless, auto, industrial,  
consumer and computer peripherals end-markets  
Key strategic alliances with global technology leaders  
including: Bosch, Ericsson, HP, IBM, Nokia, Samsung  
Strong balance sheet: cash & cash equivalents of \$2.76B \*\*

\*Source: iSuppli, 2009

\*\*As at March 27, 2010, including non-current marketable securities and cash  
restricted at JV.

Reshaping ST's Product Portfolio

Genesis  
Microchip  
NXP Wireless  
Ericsson Mobile Platforms

5 years  
R&D grants  
secured  
Manufacturing  
restructuring

ST-NXP  
synergy plan  
Headcount  
realignment  
ST-Ericsson cost  
realignment  
Micron acquired  
Numonyx

Q108 Q208 Q308 Q408 Q109 Q209 Q309 Q409 Q110  
50%  
numonyx STEricsson Micron numonyx

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Business Segment Overview

50/50 JV with Ericsson

Automotive, Consumer,  
Computer &  
Communication  
Infrastructure ("ACCI")

Industrial and  
Multisegment Sector  
("IMS")

Major Product  
Lines  
Products  
Major Customers

Home  
Entertainment  
& Displays

Computer &  
Communication  
Infrastructure

Automotive  
Products  
Group

Analog,  
Power and  
MEMS

Microcontrollers,  
Memories and  
Smartcards

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Diversified Customer Base  
2009 Top 30 OEM and Top EMS Customers

### Communications

- o Huawei
- o Nokia
- o Research in Motion
- o SonyEricsson
- o Samsung

### Consumer

- o ADB
- o Cisco/Scientific Atlanta
- o Garmin
- o LG Electronics
- o Nintendo
- o Pace
- o Panasonic
- o Philips
- o Sagem
- o Sharp
- o Technicolor

### Automotive

- o Bosch
- o Conti
- o Delphi
- o Denso
- o Marelli

### Computer

- o Apple
- o Dell
- o Eastman Kodak
- o HP
- o Seagate
- o Western Digital

### Industrial

- o Delta
- o Gemalto
- o Siemens

### EMS

- o Cal-Comp.
- o Elcoteq
- o Flextronics
- o HonHai Foxconn
- o Jabil
- o Sanmina - SCI

Note: Alphabetically listed by main application sector





Top Players in 2009 by Application

Digital Consumer

Automotive

Industrial

Wireless Communications

Source: iSuppli, ST

Manufacturing

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Lighter Asset Model  
Manufacturing Flexibility Through The Market Cycle

MARKET  
DEMAND

AVERAGE  
MARKET  
GROWTH

SUPPLIED THROUGH  
EXTERNAL FLEXIBILITY

SUPPLIED THROUGH  
INTERNAL CAPACITY

ST INTERNAL  
CAPACITY

TIME

Target Model: 80% internal, 20% outsourced

ST Manufacturing Evolution

ST STRATEGY PATH:  
IDM Flexible IDM Lighter Asset

NUMBER OF FRONT END FABs:  
17 14 9 8

WAFER PROBING (EWS):  
From Europe to a major WW center in Singapore

ASSEMBLY - NUMBER OF PLANTS:  
In Mediterranean : 3 2  
In Asia: 3 (1 China) 4 (2 China) Expand Asia

2005 end 2009

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Manufacturing Locations

Morocco

Phoenix

(final stages of closure)

(Agrate, Catania 6" & 8")

Philippines

China

(Shenzhen, Longgang)

Malta

Malaysia

Front-end fabs

Back-end fabs

Key Initiatives to Increase Capacity - 2010

Crolles2

300mm

Ramp to 3,200 w/week

32nm R&D capability

Agrate Singapore

150mm

Ramp to 18,000

w/day

Longgang

Shenzhen

g

200mm

Increase capacity in

BCD technologies and

MEMS

Q409 vs. Q410

Increase in total

capacity including

foundry = ~20%

Foundry

Electrical Wafer

Sort

Increase capacity in

wafer probing

Calamba

Increase capacity in

back-end fabs

Conclusion

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2010 Corporate Priorities

Gain market

share

Cost

reduction /

capacity

expansion

Maximize

R&D

innovation

Value from

new products

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Maximize Shareholder Value



Financial Performance & Roadmap  
Carlo Ferro  
Chief Financial Officer

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Agenda

- o Our Financial Results
  - o Our Opportunities
  - o Our Target Financial Model
-

Our Results

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4 Years of Progress Masked by Currency

- o Divested flash memories
- o 3-step merger and 50% JV in Wireless
- o Technology alliance

US\$M

- o Reduced CapEx / Sales
- o Savings from restructuring initiatives: ~\$1.1B
- o Front-end fabs reduced from 17 to 9
- o Product R&D focus:
- o Advanced Analog
- o New ASSP and ASICs
- o MEMS
- o Smart power solution
- o 32-bit MCUs

(euro)/\$ 1.20 (euro)/\$ 1.43

50% of Operating Loss of ST-Ericsson not attributable to ST

Operating Income excluding restructuring and impairment charges, as reported

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Recovered From the Recession in 2009

US\$M

Revenues

US\$M

Net Earnings

NOCF

Guidance Range:

+6% to + 12%\*\*

-]400

-]200

0

200

0

500

1,000

1,500

2,000

Q308 Q408 Q109 Q209 Q309 Q409 Q110 Q210

(est.)

Adjusted Earnings Net Operating Cash Flow (ex M&A) Revenue

5

\*Adjusted Earnings and NOCF (ex M&A) are non-GAAP measures that, the Company believes, provide us information. See appendix for definition.

\*\*Q210 revenues guidance estimate: sequential growth of between 6% and 12%.

Our Results

In US\$M, except EPS Q308 Q409 Q110 FY09 FY08

Net Revenues 2,696 2,583 2,325 8,510 9,842

Gross Margin 35.6% 37.0% 37.7% 30.9% 36.2%

Adjusted Operating Profit before

Restructuring attributable to Parent\*(1)

Adjusted Operating Margin\*(1)

210

7.8%

128

5.7%

81

4.0%

(499)

-6.8%

468

4.8%

EPS Diluted

Adjusted EPS Diluted\*

(0.32)

0.15

(0.08)

0.04

0.06

0.07

(1.29)

(0.72)

(0.88)

0.40

RONA attributable to Parent\*(1) 10.5% 7.6% 5.1% -28.3% 5.9%

Net Operating Cash Flow

(before M&A)\*

140 221 176 226 647

Effective Exchange Rate (euro)/\$ 1.54 1.43 1.39 1.37 1.49

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\*Some of the measures above are non-GAAP measures that, the Company believes, provide useful information. See appendix and below for definition and calculation methodology.

(1) Description of adjusted metrics attributable to parents:

o Adjusted Operating Profit attributable to parent = Reported Operating Profit/Loss before restructuring - 1/2 of ST-Ericsson JVS Operating Profit/Loss before restructuring

o Adjusted Operating Margin attributable to parent = Operating Profit attributable to parent / (Reported Revenues - 1/2 of ST-Ericsson JVS Revenues)

o RONA attributable to parent = Annualized Operating profit attributable to parent / (Reported Net Assets - 1/2 of ST-Ericsson JVS Net Assets)

Net Operating Cash Flow

US\$M

Net Operating Cash Flow (ex M&A)\*

-4%

-2%

0%

2%

4%

6%

8%

0

200

Q108 Q208 Q308 Q408 Q109 Q209 Q309 Q409 Q110

-10%

-8%

-6%

-200

NOCF\* NOCF/Sales (%)

\*Net Operating Cash Flow (ex M&A) is a non-GAAP measure that, the Company believes, provides useful information. See appendix for definition.

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Micron acquired Numonyx Holdings B.V. in consideration for 140M shares of Micron common stock, including assumed management's stock plan

- o Deal closed on May 7, 2010
- o In connection with the sale of its 48.6% stake in Numonyx, ST has received:
- o 66.88M shares of Micron common stock
- o They will be dealt as a financial investment

Numonyx Deal\*

Transaction

Consideration

for ST y

- o At May 6, 2010 Micron's share price of \$ 8.75, the value of the shares is \$585.2M
- o A substantial portion of such shares is hedged
- o In connection a payable of \$77.8M is due by ST to Francisco Partners
- o future full ownership of the Numonyx M6 facility in Catania, Italy,
- o ST has committed to contribute it to the new photovoltaic joint initiative owned 33% by ST; valued 60M (euro)
- o Total consideration, net of the payable, of \$580M
- o Eliminated the risk of \$225M related to the ST's guarantee to a Numonyx loan, which has been repaid in full at closing

Financial

i tt ST

- o Opportunity to accelerate the recovery of \$250M of restricted cash, due to the earlier redemption of the Hynix-Numonyx deposit

\* Based on Micron's trading price of \$8.75 per share on May 6, 2010.

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impact to o \$800M to over \$1B improvement of ST's capital structure

- o ST's estimated gain after tax to be recorded in Q210 P&L: ~\$245M



A Solid Financial Foundation

(US\$ million) Dec. 31, 2008 Dec. 31, 2009 Mar. 27, 2010

Available Cash 1,640 2,394 2,342

Restricted Cash 250 476 368

Marketable Securities, Non-current 242 42 47

TOTAL 2,132 2,912 2,757

Total Financial Debt (2,677) (2,492) (2,191)

Net Financial Position (545) 420 566

DIVESTITURES

o \$1.1B net proceeds from

M&A in 2009

S l f N i M

2016 CONVERT BOND

o Dec 2009 / Jan 2010:

repurchased \$316M

ARS LITIGATION

o February 2009: won FINRA

award ordering Credit Suisse to

o Sale of Numonyx in May pay to ST \$406M plus interest

2010: will increase liquidity

by an estimate of over

\$500M after lock-up period

o Sale of Phoenix signed in

May 2010

o In Q210 repurchased

additional \$55M

o 15.3M shares to be

cancelled

o Redemption of residual

\$673M likely due in

February 2011

o December 2009 collected \$75M

o March 2010: won in US District

Court: confirms award and

denies CS motion to vacate

o CS may still appeal but based

on the award and the Federal

Court, ST can expect to collect a

further \$354M including interest

Dividend Evolution

Company % Yield\*\*

MCHP 4.85%

TSM 4.58%

Dividend Yield as of

May 31, 2010:

MXIM 4.45%

STM 3.62%

LLTC 3.16%

INTC 2.74%

XLNX 2.49%

NSM 2.24%

AMAT 1.91%

KLAC 1.92%

TXN 1.89%

Our Opportunities

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Assets Lighter Strategy

CapEx to Sales Ratio Depreciation by Wafer

2009 Base = 100\*

5.3%

\*Based on assumed (euro)/\$ rate of about 1.30.

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Manufacturing focused to reduce wafer costs, after return to full loading

- o Currency, cash cost efficiency and roll-over depreciation are expected to contribute to about 10% wafer cost reduction from Q110 thru Q410\*
- o Further cost reduction after the final phase-out of Phoenix fab, from Q210
- o Assembly cost reductions driven by volume, shift to Asia and Gold-Copper conversion

Continuous Focus on Cost Reduction

Wafer Cost Index (Base 100 Q110\*)

\*Based on assumed (euro)/\$ rate of about 1.30.

Completing the On-Going Restructuring  
Closure of  
Phoenix  
fab by  
Q111  
~550  
headcount  
reduction  
by mid-  
2010  
~\$280M in  
cost  
savings at  
completion  
vs. Q110  
~600  
headcount  
reduction  
by end  
2010  
14

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Currency Exposure

Q110

Total Costs (COGS+OpEx) By

Currency (Q110)

Quarterly Currency Effect: +1% change

o (plus-minus)\$4 to \$5 million impact to gross profit

o (plus-minus)\$4 to \$5 million impact on operating expenses

o (plus-minus)\$8 to \$10 million on operating profit

(euro) (\*)

46%

\$

44%

50%

60%

70%

80%

90%

100%

Hedging: % of Euro exposure currently hedged\*\*

Unhedged

15

\*Euro ((euro)) includes currencies such GBP, CHF, MAD Morocco.

\*\*As of May 31, 2010.

Other 5% SEK 5%

% Hedging of

total (euro) costs

0%

10%

20%

30%

40%

Q3 10 Q4 10 Q1 11 Q2 11

Hedged before May 3, 2010

ACCI: Performance & Targets\*

ACCI

\$

Mid-term

Teens

Q410\*

US\$M

High Single

Digit

Q110

5.3%

\*Q410 assumes revenues based on a substantial continuity in market demand trends and an effective exchange rate between 1.25 (euro)/\$ to 1.30 (euro)/\$.

\*\*Segment operating results exclude, among others, unsaturation charges.

Operating Margin\*\*

Revenue

16



IMS: Performance & Targets\*

\$ Q410

High Teens

Q110

11.3%

Operating Margin\*\*

Revenue

17

\*Q410 assumes revenues based on a substantial continuity in market demand trends and an effective exchange rate between 1.25 (euro)/\$ to 1.30 (euro)/\$.

\*\*Segment operating results exclude, among others, unsaturation charges.

Wireless: Performance & Targets\*

Q410

Mitigate losses

Q110

-19.9%

US\$M

50%

losses are

minority

interest

Operating Margin\*\*\*

Revenue

ST-Ericsson plans profitability at

quarterly revenue run rate of (greater or equal) \$750

million, after restructuring is complete

18

\*Q410 assumes revenues based on substantial continuity in market demand trends and an effective exchange rate between 1.25 (euro)/\$ to 1.30 (euro)/\$.

\*\* See appendix - Q308 included 2 months of former NXP business and was before formation of ST-Ericsson.

\*\*\*Segment operating results exclude, among others, unsaturation charges.

Effective Tax Rate

- o Sustainable ETR: 16% (plus-minus) 3/4 3 points
- o Once ST moves to a higher overall profit before tax and a more

ST Operations:

~16% ETR

ST-Ericsson:

Similar structure

as ST

uniform distribution of earnings

among ST operations and

ST-Ericsson

- o Tax structure is still a competitive advantage

- o Short term ETR

Mid-Term ETR

16% (plus-minus) 3/4 3pts

Short-ST Operations:

ST-Ericsson:

- o Currently estimate a significantly higher ETR and will improve as ST-Ericsson recovers from losses

19

~16% ETR Benefit on losses

at much lower rate

2010 increase

in ETR

Our Target Model

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Financial Model\*

Transitional Model:

~ All segments at / above break-even

Low / mid-single-digit operating margin

Back to net operating cash flow of 6% to 10% of sales

Q409 - Q110 Achievements

Operating margin: 3.5% in Q4 down to 0.5% in Q110 on  
seasonally lower revenues

Excluding Wireless: operating margin 7.4% in both periods

Net operating cash flow: 8.6% and 7.6% of sales respectively in  
the two periods

ST Financial Model

9% to 12% operating margin x 1.3-1.4 net assets turns

12% to 18% return on net assets (RONA) target

Double digit net operating cash flow as % of sales

21

\*See appendix

12

....Achievable in Short Term

0.5%

9%

12%-18% RONA

or

16%-22% RONA

attributable to ST

OpEx Leverage

New Products

Manufacturing

Restructuring

Currency

Price

Q110 Prices New Products Manufacturing Currency Restructuring OpEx Leverage Q410

Operating

Margin\*

Q110

Target

Operating

Margin\*

22

\* Operating margin before restructuring charges: not a GAAP measure, please see appendix.

....by Improvements in All Segments\*

0.5%

9%

IMS: from 11% to High Teens\*

ACCI: from 5% to High Single Digit\*

Wireless: substantial reduction of losses\*

12%-18% RONA

or

16%-22% RONA

attributable to ST

Q110 Prices New Products Manufacturing Currency Restructuring OpEx Leverage Q410

Operating

Margin\*\*

Q110

Target

Operating

Margin\*\*

23

\*Product segment targets assume substantial continuity in market demand trends and an effective exchange rate between 1.25 (euro)/\$ to 1.30 (euro)/\$.

\*\*Operating margin before restructuring charges: not a GAAP measure, please see appendix.

Shareholders Value Proposition

World-wide

semiconductor

leader

Semiconductor

industry recovery

Strong capital

ST value driven

Moving towards

solid profitability

model

24

strategic

transformations

Innovative products

and expanded

customer base

structure



Appendix

- o Net operating cash flow is defined as net cash from operating activities minus net cash used in investing activities, excluding payment for purchases of and proceeds from the sale of marketable securities (both current and non-current), short-term deposits and restricted cash. We believe net operating cash flow provides useful information for investors and management because it measures our capacity to generate cash from our operating and investing activities to sustain our operating activities. Net operating cash flow is a U.S. GAAP measure and does not represent total cash flow since it does not include the cash flows generated by or used in financing activities. In addition, our definition of net operating cash flow may differ from definitions used by other companies.
- o Net financial position: resources (debt), represents the balance between our total financial resources and our total financial debt. Our total financial resources include cash and cash equivalents current and non current marketable securities short-term deposits and restricted cash, and our total financial debt include bank overdrafts, the current portion of long-term debt and long-term debt, as represented in our consolidated balance sheet. We believe our net financial position provides useful information for investors because it gives evidence of our global position either in terms of net indebtedness or net cash by measuring our capital resources based on cash, cash equivalents and marketable securities and the total level of our financial indebtedness. Net financial position is not a U.S. GAAP measure.
- o Adjusted Net Earnings is a non-GAAP measure and is used by the Company's management to help enhance an understanding of ongoing operations and to communicate the impact of the excluded items. Non-GAAP earnings excludes impairment restructuring charges and other related closure costs attributable to Parent Company's shareholders, the impact of purchase accounting (such as in-process R&D costs and inventory setup charges), other-than-temporary impairment charges on financial assets and impairment related to equity investments, net of the relevant tax impact.
- o Financial Model: Presented at May 2009 Analyst Day
- o Key Information on Consolidation / Deconsolidation:
  - o ST completed the deconsolidation of its Flash Memory Group (FMG) segment and took an equity interest in Numonyx on March 30, 2008, which is reported under the equity method of valuation with a one quarter lag in reporting.
  - o ST-NXP Wireless, a joint venture initially owned 80% by ST, began operations on August 2, 2008 and was fully consolidated into ST's operating results. On February 1, 2009 and prior to the closing of the merger of ST-NXP Wireless Ericsson Mobile Platforms to create ST-Ericsson, ST exercised its option to buy out NXP's 20% ownership stake of ST-NXP Wireless.
  - o ST-Ericsson, a joint venture owned 50% by ST, began operations on February 3, 2009 and is consolidated into ST's operating results as of that date. ST-Ericsson is led by a development and marketing company and is consolidated by ST. A separate platform design company providing platform designs mostly to the development and marketing company is accounted for by ST using the equity method.
  - o Wireless Segment: As of February 3, 2009, "Wireless" includes the portion of sales and operating results of the 50/50 ST-Ericsson joint venture as consolidated in the Company's revenues and operating results, as well as other items affecting operating results related to the wireless business.
  - o Sales recorded by ST-Ericsson and consolidated by ST are included in Telecom and Distribution



Pre-Tax Items to Adjusted Earnings\*

RESULT

NXP Wireless Inventory Step-up

Genesis in Process R&D

NXP Wireless in Process R&D

Impairment & Restructuring Charges

(attributable to Parent Company's  
shareholders)\*\*

57

76

22 65 20 240

88

21

76

481

Other-than-Temporary Impairment

Numonyx Impairment

14

300

68 139

203

138

480

OPERATING

NET EARNINGS

Estimated Income Tax effect of Adj. (46) (27) (15) (79) (141)

Adjusted Net Earnings\* 134 36 62 (627) 356

\*See appendix.

\*\*Total impairment & restructuring charges were \$96M in Q409 and \$33M in Q110.

Sustainable Technology &  
Leadership  
Jean-Marc Chery  
Chief Technology Officer

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Introduction

Technology is bringing a competitive advantage to ST in the field of multimedia convergence and power applications

- o R&D leadership & technology

segmentation

- o R&D value chain

breakdown &

management

- o Technology programs

status & roadmap

- o Summary

2

---

Technology R&D Leadership Brings:

- o Fast Time to Market
- o First device tape out
- o Device volume and yield ramp up
- o Innovation
- o Performance, power, area scaling
- o Cost of ownership, design simplicity
- o Supply Chain Multi Sourcing
- o Time to market first source
- o Second / alternative source

3

---

CMOS Logic/Analog Characteristics

Industry first

Serializer/Deserializer

for networking in bulk

silicon (CMOS32 LPH)

High

Performance

Power

leakage

Design

simplicity

General

Purpose

Low-Power

Cost of Area scaling

ownership

4

Analog /

Derivatives

Value Chain Breakdown

Fundamental

Research

Advanced

Semiconductor

R&D

Technology

Development Manufacturing

o Screen new

materials &

o Innovation in

integrated device

o Process qualification

o Technology to design

o Fast yield learning

curve

processes

& process

technology

o Design platform

qualification

o Device performance

master plan

o Multi source

enablement

Balancing technology operations with  
internal/third party competence centers:

o Advanced CMOS process through

International Semiconductor Development

Alli (ISDA) ith t t

Accelerates technology innovation and

leverages multi third party competence

centers

o Foundation / advanced R&D through joint

d i / hi tit t ti Alliance with strong concurrent

development activities

o Analog and Derivatives process through

internal cluster of Agrate and Crolles

o Distributed design enablement through

Agrate / Crolles / Greater Noida

academia research institutes cooperation

o CEA LETI: a cornerstone

o Advanced CMOS, both low power and

general purpose, R&D through ISDA

o Advanced R&D pre T0

5



Value Chain Management: Innovation

- o Process flow

- o Device architecture

...creates the difference on device ideal balanced performance vs. applications

- o Leverages best-in-class innovation vs.

T t d d t

Distributed, Cooperative R&D

6

- o Targeted products

- o Critical decision factors

- o Technologies

- o Mitigates risk of choice

- o Shares expenses

Value Chain Management: Operations

Concurrent ISDA engineering enables best-in-class and lean development techniques for:

- o Better silicon proven solution and lower cost
- o Manufacturing synchronization for wafer fab

Focused ST cluster on advanced CMOS concentrating activities of industrialization, derivatives/analog development, design platform enables:

- o Fast volume yield learning internal ramp up
- o Multi sourcing enablement
- o Fast learning cycle for time to market
- o Lean capex and opex
- o Technology differentiation
- o Best-in-class technology to design, enablement
- o Efficient design platform

7

Technology Leadership...

o Strengthening core competencies: device architecture, process integration, design enablement

Crolles:

o Low-power device

o RF add-on devices

o Embedded Dram and high performance device

o CMOS imaging sensor

o Photo lithography, TSV and 3D

o Agrate:

o Smart-Power and analog

o Embedded Nvm

o Greater Noida:

o Design enablement

....Enables...

- o Competitive innovation driven by ST's proactive approach and credibility
  - o Global and networked R&D competence centers optimized and managed by ST
  - o ST's commitment to a sustainable innovation expenses-to-sales ratio
- 9
-

Status of Key Programs

Prototyping, production ramp up Q410

CMOS 40LP Prototyping, production ramp up Q211

CMOS 32LP Prototyping, production ramp up Q311

CMOS 32LP Crolles 300 installing capacity

CMOS 28LP Designing, prototyping Q211

10

Yield Learning - D0 Trend

Tremendous improvement of time to yield generation after generation

D0 Poisson (def/cm(2))

---

U8500 Platform

Designed on ST leading-edge, LP 45nm -  
a key enabler to achieve the performance  
Technology / Product Intimacy  
Immediately ported to the LP 32nm  
ensuring economical sustainability  
and further performance improvement  
Cortex A9 @ 1.5 GHz  
12

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HKMG gate first ideal for balanced performance,  
power, area scaling, cost and design simplicity

Performance Power Area Cost CMOS32/28 LP

0

50

100

Cost Dynamic Power

Static Power

Sram Power

Area

ISDA

Competitor 1

Competitor 2

13



CMOS 65RF Prototyping, production ramp up Q310  
Other Key Programs  
CMOS F9 Production ramp up started Q309  
CMOS F10 Prototyping, production ramp up Q310  
BCD8 A Production ramp up started Q309  
BCD8 AS Prototyping, production ramp up Q310  
14

---

BCD8 A

Key description

- o Technology: BCD8A-40V 4 metal
  - Cu - 30 Mask
  - o Die size: 51mm<sup>2</sup>
  - o Challenges:
  - o 1st automotive BCD8 product
  - o New HIQUAD110 package
  - o Bonding: CU wire 1mil POA 2mils
- 15
- POA, passive, UBM (NiPd)
-

VLSI Platform R&D Model

120

130

enses

Exit of Crolles2 alliance

partners end 2007

80

90

100

110

00 = 2007 Technology R&D Expe

Current model, through

participation in alliances

resulting in R&D

productivity increase

60

70

2007 2010 Index 10

ST internal technology R&D cost (before grants)

Former partners participation to Crolles2 Alliance costs

16

CMOS Technology Roadmap  
2009 2010 2011 2012  
Q1 Q2 Q3 Q4 Q1 Q2 Q3 Q4 Q1 Q2 Q3 Q4 Q1 Q2 Q3 Q4  
Ready for production  
Ready for prototyping  
CMOS 32LP  
CMOS 28LP  
CMOS 28LP  
CMOS 20LP  
CMOS 20LP  
Low  
Power  
ST  
CMOS 28G  
CMOS 20G  
General  
Purpose  
ISDA

---

CMOS45...28 LP/G Manufacturing Source  
Technology / Source First TTM Second Alternative  
CMOS 45LP No  
CMOS 40LP  
CMOS 40G No No  
CMOS 32LP No  
CMOS 28LP  
CMOS 28G No  
Crolles 300  
One of multi-foundries source  
Another one of multi-foundries source  
18

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Derivatives/Analog Technology  
2009 2010 2011 2012  
Q1 Q2 Q3 Q4 Q1 Q2 Q3 Q4 Q1 Q2 Q3 Q4 Q1 Q2 Q3 Q4  
CMOS 65RF+Passive+Energy Mgt  
nal  
Ready for production  
Ready for prototyping  
CMOS 55RF  
CMOS 40RF  
CMOS 28RF  
BCD6 S Offline - 50/100/190V  
BCD8SH - 60/100V  
BCD8SP- 8/18/40V  
BCD9  
ST  
Analog  
Mixed Sig  
Analog  
BCD  
CMOS F10 -90 nm  
CMOS M10+-80nm  
CMOS M55  
Embedded  
Flash  
19

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Derivatives/Analog Manufacturing Source  
Technology / Source First TTM Second  
HCMOS9A Crolles 200 Foundry \*  
CMOS65/ 55RF Crolles 300 Foundry \*  
CMOS55  
eFlash  
Crolles 300 Foundry \*  
CMOSF10 Rousset 8 Foundry \*  
BCD8 Agrate 8 Catania M5  
\* One out of multi-foundries sources  
20

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The Future is Bright...  
Devices architecture (FDSOI, FinFET 3D)  
Gate FDSOI=2D FinFET=3D  
Photolithography (multiple patterning, extreme UV)  
21

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3D/Heterogeneous integration: a competitive advantage on the solution cost at same device performance, power leakage and area scaling  
Solution cost is driven by process and design complexity  
...as Innovation Drives Breakthroughs...

-

- o Communication bandwidth rapidly increasing from few Gb/s to 100Gb/s
- o Copper wire technology not able
- o Optical connections already present in servers/routers rack to rack
- Photonics on Silicon
- 22
- to sustain such data rates
- o Photonics on silicon technology allows die to die and within die optical communication
- CMOS
- wafer
- transistors metal interconnects
- F
- C
- Modulator

---

....and Aligns ST with Key Trends

Derivatives / Mixed Signal Analog trends:

- o Integration on single chip of digital analog and RF add on devices
- o Flash cell architecture, driving area scaling

Power / Analog trends:

- o Some increase in Logic content but decrease of die area with 160nm/130nm technology nodes
  - o New modules architecture and materials for better power / analog features
-

ST's Technology & Leadership: Summary

- o Enables differentiated / competitive product positioning through:
- o Device integration and device add-on for derivatives / analog
- o Design enablement
- o Specific process modules for best device performance
- o Fast yield learning cycle time techniques
- o Cooperative model allowing leveraged capture of technology innovation and risk mitigation:
- o Leverages: Full multi sourcing supply chain efficiency
- o ST's results and commitment:
- o Demonstrating competitive advantage at 40nm; strengthening it again at 28nm, then offering most advanced platforms for derivatives/analog as well
- o Moving to 20nm and beyond, with increasing complexity and facing the industry's most challenging major architecture, process, and equipment disruptions
- o Continuing to invest in deep knowledge of process, design enablement, manufacturing and their interactions

Undisputed Leader in Multimedia Convergence and Power Applications

24

Multimedia Convergence &  
ACCI Sector Overview  
Philippe Lambinet  
General Manager, Home Entertainment & Displays Group

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ACCI Focus Applications  
Automotive  
Computer &  
Communication  
Infrastructure  
Home  
Entertainment  
& Displays  
Leveraging Technology R&D / Multimedia Convergence

---

ACCI Revenues

ST Q110 Sales: \$2,325M

ACCI Q110 Sales: \$909M

39%

35%

25%

1%

34%

29%

37%

ACCI IMS Wireless\* Others

\* See appendix

\*\* Includes Imaging business

Automotive (APG)

Computer and Communication Infrastructure (CCI)

Home Entertainment & Displays (HED)\*\*

3

ST Driving Multimedia Convergence

State-of-the-Art

CPU

Audio/Video

Encode/Decode

3D GfX

Networking

Car TV

Multimedia Key Enablers

oLeading positions in all  
convergence markets

oLow-power process

roadmap

oBroad system know-how

Key Drivers

oServices

oUser interface

oLow-power

Smartphone

Netbooks

4

Automotive

---



Automotive Market Growth Factors  
More Cars, More Electronics  
CAGR 2009-2016:  
Cars: 6.2%  
Electronics: 8.5%  
250 Silicon: 10.2%  
270  
283  
298  
311 319 325 333  
20000  
25000  
30000  
35000  
arket (M\$)  
ASIC-ASSP  
MCU  
Power  
Sensors  
Electronic ignition  
Electronic gearbox  
Air conditioning  
Antilock brakes  
Navigation  
Adaptive cruise ctrl  
Airbags  
Stability control  
Night vision  
Telematics  
Bluetooth  
Start/stop  
Pedestrian detection  
Lane change  
Driver assist maps  
Car 2 car  
Internet  
Brake-by-wire  
Steer-by-0  
5000  
10000  
15000  
2009 2010 2011 2012 2013 2014 2015 2016  
Silicon Ma  
Standard  
Others  
Silicon/Car (\$)  
1975 1985 1995 2005 2015  
Central locking  
Car radio  
Seat heating  
Automatic mirror  
Xenon light  
Hybrids  
LED lighting  
Steer by wire  
Electric vehicles  
25M cars 32M cars 36M cars 64M cars 86M cars



ST: #3 in Global Automotive IC's  
ASIC-ASSP, MCU, MPU, VIPower, RF, Vision Sensors, DSP  
Products  
Power Train  
Engine Transmission  
Door Modules,  
Anti-theft  
Lighting,  
Wipers  
Body  
Electronics  
HVAC,  
Cluster  
Chassis-Safety  
Braking  
Steering  
Airbag  
Infotainment  
Car  
Infotainment  
PND  
Telematics  
GPS  
Customers Applications Segments

---

Trends and Accomplishments in Automotive

Trend:

Innovation driven by social responsibility

- o Emissions, safety, connectivity

Trend: Large emerging markets with

different needs and

requirements

ST Strategy:

Innovate with the leaders ST Strategy:

Fast time to market at

different feature and

cost points

Accomplishments:

- o 32-bit MCU awarded by North

American OEM for a new

global transmission platform

- o Chosen as a supplier of a next

generation powertrain MCU platform

with 55nm embedded flash for a major Tier 1

- o Chosen to provide a full IC portfolio for Asia

airbag platform of major European Tier 1

Accomplishments:

8

- o 1st worldwide Li-Ion battery manager IC in a mass production plug-in hybrid vehicle

- o Selected to develop a new radar baseband IC for adaptive cruise control for a US Tier 1

- o MCU award by the fastest growing Chinese carmaker for all powertrain

- o Steady #1 in China, doubling revenue in auto electronics every year from 2006 to 2011

- o Gained 100% share of car radio tuner for two major Japanese Tier 1s for China

Computer & Communication  
Infrastructure

---

Leader in Digital and Analog ASIC  
CARTRIDGE HDD PRINTER NETWORK  
Motor  
Controller  
Digital  
ASIC  
BS RF &  
Active  
Print  
Heads  
& Head  
Drivers  
BCD  
& SOC  
HCMOS  
Cables  
Drivers  
MFLD BICMOS  
TOP 1 TOP 2 TOP 3 TOP 3  
10

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Market Trends and Strategy in ASIC

- o Cloud computing will fuel the next wave, generating increasing demand for (green) infrastructure and transforming all applications in cloud conscious clients
- o ASIC continues to be an effective win-win model for CCI customers and ST continues to be committed to it

Cloud Computing Web Connected Internet Traffic Green Systems

- o The strategy: expanded product offering and flexible business model
  - o Key achievements
  - o Significant design wins in the areas of communication infrastructure and printers in digital
  - o Launch of the first 32nm bulk platform for networking applications
  - o Expansion of the SPEAr family with the launch of the 1300 series
-

CCI Growth Drivers  
BiCmos ASIC  
for AOC and RF  
PrintHeads for  
InkJet Printers  
Digital ASIC for  
Networking  
Printer SOC and  
SPEAr eMPU  
12

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Home Entertainment & Displays

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Consumer Electronic Trends

- o Analog switch-off
- o Increasing demand for Pay TV and FTA satellite
- o New connected services 150

200

250

Mu STB Market Evolution

- o Content aggregation - broadcast & IP
- o Services across all consumer devices
- o Exciting entertainment experience
- o 3D stereoscopic TV
- o GUI technologies - 3D graphics, MEMS...
- o LED BLU

o 0

50

100

250

300

DTV Market Evolution

Mu

Environmental factors

- o Power consumption
- o Green production

0

50

100

150

200

Source: iSuppli, IMS

1

Our Application-Platform Evolution

Gen. 1 Gen. 2 Gen. 3 Gen. 4

Fully open  
connected

New services

New UI

Best

performance

HD H.264

market

platform

internet TV

enabler / cost ratio Client / Server

STi7100

STi7103/FLI106xx

STi7105

STi7104/FLI326xxH

STi7108

FLI7510

7109, 5202 7111, 7141, 7200

5211, 5206, ...

71xx, 52xx

STi7xxx

FLi7xxx

MPEG2 1000 DMIPS CPU Dual CPU & L2 cache Multi-core SMP CPU

Mass production Mass production In design

Production: 2007 a(3) Production: 2009 a(3) Production: 2010 a(3) Production: 2011 a(3)

Samples now

>5000DMIPS

Introduction of:

Dual 1080p60 decode

HD encode

Display Port, MOCA 2

>2000 DMIPS

Introduction of :

1080p60 decode

3D GL-ES2.0

MOCA 1.x

Introduction of :

AVS HD

DDR2

e-SA

HED H1 2010 Highlights

- o Gen. 2 based STB massively deploying
- o Mass production started in June 2009
- o 55nm process with >10 products families
- o > 50 customers in production now
- o > 50% of ST total STB shipments from 2010
- o Gen. 3 getting ready for ramp up in 2010
- o Gen. 3 introduced at CES 2010
- o Freeman/FLI7510 solution for DTV designed in at multiple partners
- o >20 partners enabled with STi7108 platform
- o Develop new category of STB & mediacenter
- o Develop new software for new services
- o RIA, GUI, gaming, mediaserver, ...

16

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Conclusion

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Multimedia  
convergence  
o Power  
management  
o (less than or equal)45nm CMOS  
o BCD, BiCMOS  
o Microfluidics  
o Analog/RF  
P fl Broad/Deep  
ACCI Key Strengths  
Powerful  
Technologies  
Product  
Portfolio  
Consolidate  
Leading  
Positions  
o ASICs  
o Platforms  
o Innovative  
products  
o Excellent service  
/ support  
Flexible  
Business  
Models  
Serving  
Market  
Leaders  
18

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ACCI Strategy

DTV

Networking

32-bit MCUs

for Auto

- o Expand market share
- o Leverage key strengths
- o Capture larger share of new markets / new product generations
- o Diversify / grow customer base

Selected

capacity

expansion

Multimedia

convergence

SPEAr

platform

Automotive

industry

recovery

- o Participate in market recovery
- o ACCI still significantly below pre-crisis level
- o Favorable market trends in targeted segments
- o Solid financial position is a competitive advantage
- o Increased focus of R&D effort
- o Shared platform
- o Innovative ASICs business models
- o Collaborate with key customers, partners and research institutions

o Optimize manufacturing

Increase man fact ring efficiencies

Key drivers to grow sales

and profitability

19

- o manufacturing o Align capacity with demand
- o Accelerate development / move to new processes
- o Improve profitability towards high single digit operating margin by the end of 2010 and in the teens in the mid-term

IMS Overview &  
Advanced Analog & Smart Power  
Carmelo Papa  
General Manager, Industrial & Multisegment Sector

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IMS at a Glance

2009 IMS key facts

TAM = \$42B

Billing = \$2.66B

Market Share = 6.3%

Innovation Results:

- o 5 new products per day

- o ~20% of sales with products less than 2 years old

Schaumburg

Boston Prague

Catania

Taipei

Tokyo

Seoul

Shanghai

Noida

World Wide Competence Centers

- o 2 new system solutions (boards) per week

Technical Resources:

(designers, application engineers, technical marketing)

ANALOG & MEMS

45%

DIGITAL

35%

2

p

Singapore

Technical support located near customers

in all sales regions

POWER DISCRETE

20%

IMS Results & TAM Evolution

OEM

EMS

By Customer Type

2015

(US\$B)

CAGR

(2010 ~2015)

Digital 19 5.8%

Al & MEMS 32 6.4%

Distribution

Industrial

Consumer

Computer

Automotive

Telecom

By Market Segment

Analog 6.4%

Power Discrete 20 5.7%

Total IMS 71 6.0%

Power

2015 TAM Split

Greater

China &

South

Asia

EMEA

Japan &

Korea

America

By Region

Digital

Analog &

MEMS

Discrete

Source: WSTS, STMicroelectronics

IMS Billing Split & Evolution

36%

38%

40%

42%

44% IMS Sales weight

2009 Sales Split

22%

24%

26%

28%

30%

32%

34%

Q1'06 Q2 Q3 Q4 Q1'07 Q2 Q3 Q4 Q1'08 Q2 Q3 Q4 Q1'09 Q2 Q3 Q4

Power Analog & MEMS Digital

4

IMS: Analog

\*R k i f t t t l S T A 1 I C 1

Analog Ranking 2009

Analog ICs\* # 2

Key product family Key target applications

Power management ICs Power supply, solar, lighting

Mixed signal ICs Mobiles, peripherals, portable medical

Ranking refers to total ST Analog ICs sales

- o Ability to integrate analog and power in a single chip or in a single package in power conversion and power management applications

Competitive Advantages:

Battery management ICs Mobiles, PDAs, e-Books

LED driver ICs Street lighting, building, panel arrays

- o System know-how enabling the design of dedicated ICs for complex applications and a variety of reference designs for medium and small customers

- o Ability to deliver system solutions including sensors, analog ICs, microcontrollers and power discrete

- o The world's largest and most cost effective 6" front-end fab in Singapore

5

Source: iSuppli, ST

IMS: MEMS

Key product family Key target applications

2 or 3-axis

Accelerometers

PDAs, mobiles, toys, notebooks,

multimedia devices

MEMS\* Ranking 2009

All Segments # 1

(except Automotive)

o Integration in a single package of MEMS, data converters and RF transceivers for  
t t k

\*MEMS accelerometers & gyroscopes

Competitive Advantages:

Gyroscopes Games, camcorders, camera  
stabilization, GPS

Microphones Games, mobile phones, laptops

smart sensor networks

o Proprietary innovative silicon and packaging technologies for miniaturization  
and ultra-low-power fitting medical and portable applications

o First in the world to adopt an advanced 8" inch wafer fab (Agrate)

6

Source: iSuppli, ST

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IMS: Power Discrete

Key product family Key target applications

HV Power MOSFETs Power supply, lighting, solar

Rectifiers Power management

Power Discrete Ranking 2009

Power MOSFET (High Voltage) # 1

Protection & IPAD # 1

o The widest range of power technologies and packages from low to very high voltage (MOSFET, IGBT, Bipolar, IPAD, Rectifiers) offering the highest efficiency in ACS switches Home appliances

Protections & IPAD Mobiles, USB/HDMI

interfaces, wired data transfer

Competitive Advantages :

Thyristors # 1

Rectifiers & power diodes # 3

the most demanding applications

o Expertise in composite materials (SiC, GaN) for high frequency and very high temperature applications (electric cars, photovoltaic converters, wind generators)

o Extremely competitive manufacturing machine (Singapore, Longgang, Shenzhen)

7

Source: iSuppli, ST

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IMS: Digital

Key product family Key target applications

RFID & RF EEPROMs Access control, tracking systems

Microcontrollers Low-power medical and portable

i

Digital Ranking 2009

EEPROM, EPROM # 1

Smart Card # 3

- o Common technology and high-performance core (ARM(R) Cortex(TM)) platforms for smartcards and microcontrollers

- o Ultra-low-power technology suitable for battery operated and medical applications equipment

32-bit smartcard ICs Mobile phones, data security

Competitive Advantages:

Product portfolio

- o Complete hardware and software solutions for secure applications (STB, banking, access control, NFC)

- o Special set of peripherals for connectivity (RF, ethernet), human machine interface (touch sensing) and real time control (motor control timers)

8

Source: iSuppli, ST

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IMS: Key Strengths

- o Analog drivers
- o High voltage power MOSFET
- o Rectifiers

Consolidated

IMS Key Areas

Lighting

Switch mode

power supply

Motor

control

- o Smart power ICs
- o Power transistors
- o Microcontrollers
- o Analog ASSP ICs
- o Microcontrollers
- o Power transistors

9

Secure Mobile

transaction

o IPAD

o MEMS and sensors

o Audio amplifiers oSmartcards



Expanding into New Focus Areas

10

Source: iSuppli, Semicast

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Innovation is Still IMS Key Driver

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System Innovation

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Complete reference designs  
(Hardware & Software) for  
medium and small accounts

Our System Approach

- o More than 550 reference  
designs available to  
support our worldwide  
design-in activity

13

- o Innovative new product definition  
thanks to feedback from customer  
system know-how

System Innovation in Energy

- o Hybrid Electric Traction
- o Motor drivers
- o Power conversion
- o Battery-cell management
- o Fast battery charger
- o Photovoltaic panel converters
- o SmartGrid

14

- o Smart energy metering
  - o Smart appliance plug
  - o Power-line modem
-

System Innovation in Automation

- o Home automation through advanced wired (200 Mbit/s) and wireless connectivity
- o Application Specific Integrated Modules (ASIMs) for robotics and industrial automation
- o Sensor networks for building automation

ASIM

Embedded motor drive module, remotely controlled by ethernet

15

- o Low-power energy harvesting and storage

Flexible rechargeable battery

---

System Innovation in Healthcare  
o Remote patient monitoring  
o Blood pressure  
Portable distributed diagnostics  
and remote monitoring  
Flexible lens for  
eye pressure  
monitoring Electro  
o Heart beat cardiogram  
o Electrocardiograph  
o Eye pressure sensor  
o Movement reconstruction  
o Rehabilitation  
Insulin  
nano pump  
Temperature  
sensor  
Pressure  
sensor  
16  
o Fitness  
o Patient treatment (i.e.  
insulin pump)  
Movement  
recognition  
Step counter

---

Technology Innovation

---



Emerging Applications Require Smart Integration:  
Moore's Law and More than Moore  
Sensors, Biochips  
Actuators  
HV  
Analog/RF Passives Power  
"More than Moore": Diversification  
zation  
CMOS: CPU, Memory, Logic  
130nm  
90nm  
65nm  
45nm  
32nm  
SiP  
SSooCC  
re's Law ": Miniaturi  
18  
Baseline C  
22nm  
....  
V  
Beyond CMOS: Quantum  
Computing, Molecular  
Electronics Spintronics

---

ST Enabling Technologies: "More than Moore"

- o MEMS & smart o Flexible ICs  
sensors

- o Harvesting & thin film  
batteries

- o Advanced BCD,  
BCD-SOI

- o New materials: SiC &  
GaN

- o Ultra-low-power  
technologies

19

- o Advanced packaging &  
system-in-package

- o 3D heterogeneous  
integration / TSV

- o Microfluidics

Product Innovation

---

Smart Meters  
Smart Meter IC  
MICROCONTROLLER  
ETHERNET  
PORT  
INPUT  
DSP COPROCESSOR OUTPUT  
DATA CONVERTER  
Smart Meter IC  
System on Chip  
POWER SUPPLY PROTECTIONS DISCRETE  
COMPONENTS  
SOFTWARE  
TIMERS ENCRYPTION EMBEDDED  
Data Security  
ACCELERATOR  
ENGINE  
VOLT  
AMPLIFIERS REG. MEMORIES  
ANALOG MODEM  
FRONTEND  
21  
More than 40M smart meters with ST's power-line  
modem connectivity already installed in the field  
Source: ABI Research, ST  
Target Applications:  
o Electricity meters  
o Water meters  
o Gas meters  
Smart electricity meters TAM 2009: 76M units  
CAGR 2010-2013: ~18%

---

Micro Inverter Modules

- o Maximizing energy output (MPPT)
- o Energy monitoring (daily, monthly, yearly, etc.)
- o Diagnostic and anti-theft & anti-tearing protection
- o Reducing operation cost due to modularity

Cool Bypass Switch

Micro Inverter

MPPT

Max Power Point Tracker

DC/DC

Remote

Monitoring &

PV Panel Control

Converter

DC/AC

Inverter MOSFET

SiC

PLM

Power Line Modem

Monitoring &

Diagnostics

(Energy Level Faults etc )

Electronics on panel value from \$1.50 to \$15

PV d t i t h

PLM

Target applications:

- o Level, Faults, etc.) energy production growth
- o 2010 a(3) about 7 GW  
(~35 million single photovoltaic panels)

- o 2020 a(3) about GW

22

Source: European Photovoltaic Industry Association, ST

LED Lighting Driver ICs  
Driving LEDs using AC-DC solutions  
.... more light with  
Luminous efficacy  
LED >100 lm/W  
Driving LEDs using DC-DC solutions  
g  
less energy  
TL 70 lm/W  
CFL applications:  
LED Array Drivers  
50 lm/W  
Target o Display & signs  
o General illumination  
o Backlight LED TAM 2009: 63B units  
Filament 15 lm/W  
o Signal lighting  
Source: iSuppli  
CAGR 2010-2013: 30%

---

Motherboard Power Management ICs  
o Enabling next generation motherboard  
power management solutions  
Multi Segment ICs Motherboard Dedicated ICs  
CPU power management  
controllers  
High density DC-DC  
controllers  
High efficiency switching  
regulators  
Single and multi phase DCDC  
controllers Multi output controllers  
Multi output regulators  
LED backlight drivers  
Low power consumption  
switching regulators  
Server  
24  
TAM 2009: \$2.6B  
CAGR 2010-2013: ~12% Source: iSuppli  
Target applications:  
o Desktop  
o Laptop  
o Server  
Laptop Desktop

---

MEMS Gyroscopes  
Driving direction Sensing direction  
No Angular rate  
(Pitch axis)  
Angular rate  
(Pitch axis)  
Target applications:  
S t h  
25  
Source: iSuppli  
TAM 2009: ~\$526M  
CAGR 2010-2013: ~13%  
o Smart phones  
o Robotics  
o Navigation  
o Cameras  
o Gaming

---



Microcontroller "STM32W"

.... embedding radio

frequency function

o IEEE 802.15.4 open flexible reconfigurable platform

Low power microcontroller

product family, ...

Target Applications:

o Smart meters

o Home & building automation

26

System-on-Chip solution

Microcontroller, radio and firmware

o Wireless sensor networks

o Healthcare

o Consumer

o Remote control

o Home automation 32-Bit MCU\* TAM 2009: \$3.8B

Source: WSTS CAGR 2010-2012: >10%

\*Includes Automotive

---

Flexible Eye Lens for Glaucoma  
7.5 age  
Population and aging increase  
Flexible Lens IC for wireless sensor  
for Continuous eye pressure monitor  
o Contact lens (30m thickness)  
27  
Therapeutic sales for  
ophthalmology disorders exceeded  
\$12B in 2009  
Over 7.5 million suffer from age-related  
macular degeneration  
o Pressure sensor  
o Continuous remote monitoring  
o Very low-power RF data transfer  
Source: World Health Organization  
Target applications:  
o Remote patient monitoring

---

3D Ultrasound Scanner ICs

- o Miniaturization and low-power ICs allow electronics migration from centralized computer to ultrasound beamer

Old System New System

Solution Integrating:

- o Power management IC array

- o Microcontroller

3D Image 2D Image

28

- o Analog front-end and data converter

Source: Semicast

TAM 2010: 83M units

CAGR 2010-2013: 11%

Target application:

- o Echographs with color and 3D

Integration

---

- o Focus on high-margin segments (energy, automation, healthcare)
  - o System approach to deliver complete solutions to the market
  - o Boost high-performance, high-margin analog products leveraging on our IMS Strategy
- strong position in MEMS and power management
- o Pervade the market with microcontrollers and secure access products based on ARM core leveraging on:
    - o Ultra-low-power technologies for portable and healthcare applications
    - o Complete set of analog peripherals including wireless connectivity
    - o Maintain our leadership in power discrete supporting:
      - o High-volume and cash-generating products
      - o New high-margin products utilizing new materials (SiC and GaN)
    - o Improve profitability towards high teens operating margin by the end of 2010 and above 20% in the mid-term
-

TOWARDS TRANSFORMATION  
Gilles Delfassy, President & CEO

---

2009: FORMATION

2010: TRANSITION & TRANSFORMATION

---

FIRST QUARTER SUMMARY

- o Net sales \$606 million
- o Adjusted operating loss \$114 million

Net sales

Adj. oper. loss

- o Net cash \$120 million
- o Restructuring plans on track
- o ~((50% savings of \$230 million plan
- o \$115 million plan savings from H2

2010

Q1

2009 2010

Q1

Q2

Q3 Q4

3

- o R&D efficiency program
- o Integration of IT systems

2009 (Pro-forma):

Net sales: \$2.7B

Adj. operating loss: \$440M

June 3, 2010

2010 PRIORITIES

Competitive cost structure

New portfolio

Pursue profitable growth

4

u sue p o t a b e g o t

Focus on priorities and fast transition

June 3, 2010

---



TRANSFORMING THE COMPANY

E & f h o High-value entry

- o Smartphones
- o Connected devices
- o Application engine
- o Modem
- o Connectivity
- o Diversified customer portfolio
- o Open/complete platforms
- o Entry feature phones
- o Modem only
- o Three big customers
- o Custom solutions

5

p p p

o Europe and Asia o Global

June 3, 2010

---

MOBILE PLATFORMS AT THE HEART OF CONVERGENCE

6

Manage the complexity is crucial

June 3, 2010

---

DELIVERING COMPLETE PLATFORMS IS KEY

Connectivity

GPS, Bluetooth, HDMI

WiFi, USB, FM

Multimedia

3D graphics, HD video,

audio, imaging

Power management

and RF

Modem

2G, EDGE, WCDMA,

TD-SCDMA, HSPA+, LTE

Processors

Multi core architectures,

5000DMIPS

low-power consumption

Software

Open OS web browsing

7

OS, Requirements on wireless semiconductor players are evolving accordingly

June 3, 2010

---

ENABLING A CONNECTED WORLD

Thin

Modems

Platforms

LTE / HSPA+ Mobility

Best combined UL/DL  
performance

Data in every region

M720

LTE/HSPA

M340

HSDPA

M570

HSPA+

M700

LTE

DRIVING MOBILE BROADBAND

EVERYWHERE

Mobile Broadband and M2M Devices

UMTS/ 2G/EDGE

HSPA

LTE TD-]SCDMA

Entry

Application

Processor with

Integrated

Modem

Platforms

High-performance

Smartphone platforms

U8500

2 (multiply) 1GHz

HSPA+

U68XX

5209

EDGE

M6718

TD-HSPA

U67XX

U6715

U5500

2 (multiply) 600MHz

HSPA+

TD

THE BEST SMARTPHONE PLATFORMS

FOR ALL TIERS

High-end and mid range smart devices

8

Y

Platforms Internet and Multimedia

enabled solutions

Single-chip 2G & EDGE

HSDPA

U33x

HSPA/HSDPA

WCDMA

T72XX

TD-HSDPA

HSDPA  
E4908  
EDGE  
G4850/52  
GSM/GPRS  
E4910  
EDGE  
T6718  
ADDING VALUE TD-HSPA  
TO AFFORDABLE DEVICES  
High value entry devices  
June 3, 2010

---

PLATFORM PORTFOLIO

Thin

Modems

Platforms

In Production Announced

LTE / HSPA+ Mobility

Best combined UL/DL

performance

Data in every region

M720

LTE/HSPA+

M340

HSDPA

5209

EDGE

M570

HSPA+

M700

LTE

M6718

TD-HSPA

UMTS/ 2G/EDGE

HSPA

LTE TD-]SCDMA

Entry

Platforms

Application

Processor with

Integrated

Modem

Platforms

Internet and Multimedia

enabled solutions

High-performance

Smartphone platforms

U8500

HSPA+

U68XX

HSDPA

U67XX

WCDMA

U6715

HSDPA

U5500

HSPA+

TD

9

Connectivity and

Enhancements

CW1200 Complete Platforms

WLAN

CG2900

BGF

AV5230

Audio PTE

AV8100

HD TVout

Single-chip 2G & EDGE

U33x  
HSPA/HSDPA  
T72XX  
TD-HSDPA  
E4908  
EDGE  
G4850/52  
GSM/GPRS  
E4910  
EDGE  
T6718  
TD-HSPA  
June 3, 2010

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ADDING VALUE TO AFFORDABLE DEVICES

More features at low cost  
High-value entry devices  
Enhanced connectivity and multimedia  
Integration to single-chip  
Best-in-class power consumption  
Smart multimedia for all  
Linux/Android(TM) support  
WQVGA screens, touch-screen and H.264 video  
HSDPA for fast content sharing  
10  
Single-chip ultra low  
cost  
Dual SIM/Dual standby  
USB charging  
Single-chip Quad-band  
EDGE  
Low power , MM touchscreen  
QVGA & 3Mpixel camera  
G485X E49XX  
Affordable  
Linux/Android  
HSDPA  
WQVGA & 5Mpixel  
camera  
U6715  
TD-HSPA  
Quad-band EDGE  
WQVGA & 5Mpixel camera  
T6718  
June 3, 2010

---



HIGH VALUE ENTRY GAINING MOMENTUM

U6715

- o Ramping with four new customers in Asia
- multiple models

- o Interest from operators across the globe

E49xx

- o Two top customers for EDGE & GPRS versions

11 June 3, 2010

Affordable

Linux/Android

HSDPA

WQVGA & 5Mpixel

camera

U6715

Single-chip Quad-band

EDGE

Low power , MM touchscreen

CONNECTIVITY INTEGRATED INTO COMPLETE  
PLATFORM SOLUTIONS

- o Selected by two additional U8500 customers
- o Further momentum coming from Asia

12 June 3, 2010

BT/FM/GPS

First 45nm Combo

Leading footprint size

CG2900

802.11a/b/g/n

( 50mm2 BOM

Integrated FEM, SMPS

CW1200

HDMI/CVBS combo

Full HD 1080p

7.1 audio surround

AV8100 AV5230

102 dB SNR

Integrated headset AMP

Playback Time Extender

THE BEST SMARTPHONE PLATFORMS FOR ALL TIERS

U8500: Top performance at low power  
High and mid-end smart devices  
Dual-core processors >1GHz  
HD-multimedia 1080p  
Full web-browsing experience  
Mobile broadband with HSPA+  
Powerful 3D graphics - OpenGL ES 2.0  
Touch displays, dual screen  
Complete solutions with Open OS

13

Dual-core SMP Cortex A9

HSPA+

1080p HD & advanced 3D

Dual-screen support

U8500

TD-HSPA

HSPA+

LTE

Thin modems

Affordable Linux/Android

HSDPA

WQVGA & 5Mpixel camera

U6715

Dual-core SMP Cortex A9

HSPA+

720p HD

Advanced 3D

U5500

June 3, 2010

U8500

---

THE MOST ADVANCED SMARTPHONE PLATFORM  
U8500

- o Selected by two additional customers
  - o Four customers overall since launch
  - o Supporting various OS
  - o Symbian and Linux, incl .Android
- 15 June 3, 2010
-

DRIVING MOBILE BROADBAND EVERYWHERE

Connected devices and embedded mobility

Advanced modems

HSPA+ mobile broadband for all devices

LTE, the next evolution for high-speed data

TD-HSPA broadband modems for China

Optimized modems for numerous applications

Modem technology from GSM to LTE

Supporting devices from smartphones and netbooks to  
consumer electronics and M2M

16

LTE /HSPA+

Proven hand over

100 Mbps

HSPA+ 21 Mbps

Simultaneous full speed

UL/DL

Best in class thermal heat

Dual mode

TD-HSPA & quad band

EDGE

M720 M570 M6718

June 3, 2010

DRIVING MOBILE BROADBAND EVERYWHERE

M570 - M720

Multiple design wins for our advanced modem solutions

17

HSPA+ 21 Mbps

Simultaneous full speed UL/DL

Best in class thermal heat

M570

LTE /HSPA+

Proven hand over

100 Mbps

M720

June 3, 2010

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ADDRESSING MODEM EVOLUTION

Challenges

Increasing air  
interfaces

Then Now

TD

LTE

HSPA+

New ST-Ericsson

ltd

- o Software-defined radio access

- o LTE 100Mbps, HSPA+ 42Mbps

- o Target >2X power

improvement

- o Scalable for cost

Power management

needs

2G

2G/3G

EDGE multi-mode modem

architecture

Increasing adoption

BT of connectivity

FM

BT

GPS

WIFI

- o Co-existence built-in

- o Combos & platform

integration

Increasing

adoption of

connectivity

18

- o Building on existing LTE

solution

- o Single SW and HW platform

- o Drastic reduction of testing

Size & cost

June 3, 2010



2010 PRIORITIES

- o Competitive cost structure
- o New portfolio
- o Prepare the company for future, profitable growth

19

Focus on priorities and fast transition

June 3, 2010

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Region Americas:  
The Land of Opportunity  
Robert Krysiak  
General Manager, Americas Region

---

Americas 2009 TAM: \$35B

Military/Space

Automotive

4%

Top 10 Americas OEM

2009 Spending

Top 10 OEMs:

~62% of TAM

Computer

Platforms

36%

Consumer

7%

Industrial

7%

Medical

4%

10%

2

Source: iSuppli

Computer

Peripherals

Wireless 6%

15%

Americas Forecast

o Consumer CAGR ~ 16%

driven by:

o Game consoles

o LCD TV

A t t i CAGR 12%

o Americas TAM

o 2009-2014 CAGR ~ 7%

o Automotive ~ 20,000

30,000

40,000

50,000

60,000 TAM Revenues Forecast

1.0

1.2

1.4

1.6

1.8

2.0

2.2

Application Growth Forecast

US\$M

3

Source: iSuppli

0

10,000

2009 2010 2011 2012 2013 2014

0.8

2009 2010 2011 2012 2013 2014

Automotive Consumer Data Processing

Industrial Wired Wireless

Americas Ecosystem Strength  
Design Houses  
Venture Capital  
Startups  
ederal Stimulus  
Universities  
OEMs  
Regulatory  
4

---

North America Economic Environment

US Trade Deficit

- o Deficit growth is validating the evidence of recovery from the worst global recession since World War II
- o US exports grew faster than imports in 2010 despite a stronger \$ vs. (euro) driven by industrial supply, farm products, semiconductors and strong expansion in China

US Imports

- o Impacted by lower crude oil prices

US Unemployment

- o Rose to 9.9% in April from 9.7% in March

ST Americas end-of-quarter BiBA:

doubled from Q1 2009 to Q1 2010

5

ST Americas: Revenues Trend

- o ST Americas is growing the Domestic market while leveraging the "Design Influence" to expand offshore growth
- o Bridging Americas with China and A/P on common strategic plans
- o 1Q10 affected by seasonality

Americas Domestic Revenues =

US\$M 13% of ST

"Design

Influence"

1Q09 2Q09 3Q09 4Q09 1Q10

Domestic WW

Influence

6



Americas  
Computer Peripherals & Communications  
Infrastructure

---

Communications  
Communications Infrastructure  
\$100M  
Leading Americas  
i ti  
ST well positioned  
L di A i  
Smart Phones  
ST Americas:  
2012 potential new  
business target  
\$120M  
communications  
players:  
Cisco, HP, Google,  
Microsoft,  
Facebook, etc.  
Mobile data traffic  
to increase 39X  
from 2009 to 2014\*  
to outperform the  
market utilizing  
32nm ASIC IP  
portfolio & SPEAr  
platform  
ST Americas won 3  
major 32nm ASICs  
in Q1 2010  
Leading Americas  
smart phone  
players:  
RIM, Apple,  
Motorola &  
HP/Palm  
Apple & RIM  
account for >50%  
of cell phone  
manufacturer's  
operating profit  
ST Americas  
mainly provides  
MEMS solutions  
and Imaging  
products  
ST Americas  
ramping innovative  
gyroscopes in Q1  
2010  
Source: Cisco  
8



SPEAr - New Flexible ARM Cortex Platform  
Structured  
ASIC  
2 x ARMv7  
SPEAr1600  
Industrial  
Automation  
Telecom  
Networking  
D ki  
VoIP/Videoconference  
Security  
MID  
SPEAr1320  
SPEAr1310  
SPEAr1300  
SPEAr1340  
\$50M  
ST Americas  
targeting key  
players  
IP Processing  
VoIP  
Smart Meters  
High-end  
Docking  
Thinclient  
Net-PC  
SPEAr2A9  
SPEAr1330  
ST Americas:  
2012 potential new  
business target  
Residential  
Gateways  
Access Points  
9

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Computer Peripherals  
Leading Americas  
Shifting from  
disposable to  
permanent print  
ST is leading  
ST expanding in  
Digital & Analog  
ASICs Secure  
Printers  
+integrated WiFi  
\$150M  
Printer Players:  
HP, Lexmark,  
Kodak  
heads and from  
wired to wireless  
connectivity  
semiconductor  
supplier offering  
complete solutions  
ASICs, Micros, Touch  
Sense, WLAN &  
Power  
Data Storage Samsung  
Electronics  
9%  
Western  
Digital  
Top 5 HDD OEMs - Q110\*  
ST Americas:  
2012 potential new  
business target  
Leading Americas  
HDD Players:  
Western Digital,  
Seagate  
2010 market to grow  
19% driven by  
increased data  
demand - video,  
mobile & cloud  
storage\*  
ST provides Digital  
ASICs and custom  
power products to  
the market leaders  
Source: iSuppli  
Toshiba/  
Fujitsu  
11%  
Hitachi  
Seagate 18%  
31%  
31%  
10



Americas:  
Consumer

---

Consumer Convergence

- o Mobile Internet Devices (MID); Smartbooks, Tablets, Netbooks...transforming the way consumers work/play
- o In 5 years MIDs will dominate the semiconductor TAM in the new PC/Consumer market
- o Apple, PC OEMs, Microsoft, Google, and their ODMs will be the dominate players in the MID market

Video Peripherals Power Security Custom

ST Selected Products

3D Graphics

Codecs

MEMS

Display Port

Touch/proximity sensing

System Power

TPM

Brand Protection

Encryption engine

Near Field Power

Security

Peripherals

LED/OLED Drivers

AC/DC controllers

Advanced ARM

processors

Image Quality

12



STi7108: Best-in-Class H.264 SoC for STB  
o 2000 DMIPS host performance  
o Integrated 3D Graphics GPU  
o Enhanced Video  
Set Top Box  
ST ki  
o 1080p60  
o Full motion HD 3DTV  
1st ST product with ARM Cortex-A9 due in H2 2010  
\$110M  
Combining  
traditional STB  
services with  
Internet  
Expanding the  
Consumer  
experience with  
stereoscopic  
vision  
ST product  
roadmap tuned  
for new features  
and services  
working on  
current/next  
generation set  
top box  
platforms with  
top US OEMs  
ST Americas:  
2012 potential new  
business target  
13

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MEMS  
Pervasion of  
i  
Motion sensor  
k t Integration of  
MEMS d t  
ST Americas  
hi i l  
MEMS  
\$200M  
MEMS in  
consumer devices  
continues to  
significantly  
increase  
market CAGR  
(2009-13) of 15%  
and 19% for  
accelerometers &  
gyros, respectively  
MEMS, data  
converters & RF  
transceivers is  
competitive  
advantage  
shipping large  
volumes of  
accelerometers &  
ramping gyroscopes  
in Q1 2010  
ST Americas:  
2012 potential new  
business target

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Americas:  
Automotive

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Auto Communications  
#1 in  
#1 in  
Satellite  
Radio  
Strategic  
supplier of  
GPS to  
Garmin  
Innovation in  
auto  
communications  
market is lead  
by the Americas  
Consumer  
Power  
Amplifiers  
GPS  
device  
connection

---

Auto Safety  
Advanced  
battery  
charging  
Silicon partner  
for Mobileye  
Partner with  
Navteq for ADAS  
Innovation in  
auto safety  
market is  
lead by the  
Americas  
Unique  
data  
Energy  
efficienc  
GaN  
partnership  
for advanced  
power  
solutions  
solution to  
LG  
mapping  
utilization  
efficiency  
with  
PEV/HEV  
17

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Automotive Market  
US autos are Advanced Build on our  
t iti  
ST Americas  
i i k t  
Automotive  
\$140M  
BCD  
VIPower  
MPU  
32BIT MCU  
leaders in silicon  
content and  
vehicle  
production  
concepts utilizing  
GPS, car-to-car  
and grid  
communications  
strong positions  
via partnerships  
and offer a full  
range of system  
components.  
gaining market  
share in MCUs and  
achieved major  
powertrain MCU win  
at a US OEM  
Growth by Technology Family  
ST Americas:  
2012 potential new  
business target  
2009 2010 2011 2012 2013 2014 2015

---

Americas:  
Industrial & Medical

---

LED Lighting  
Great potential  
9.5W LED replaces  
i d t  
ST is #1  
li t t Major design wins  
LED Lighting  
\$45M  
200  
250  
300  
in general  
illumination  
with 2009 to  
2012  
CAGR>90%  
80W incandescent:  
market price (\$35,  
payback time (lyr &  
15 year bulb life  
supplier at top 5  
lighting  
worldwide  
manufactures  
in US region  
generating  
potential billing  
growth with  
CAGR)300%  
LED Driver Market  
ST Americas:  
2012 potential new  
business target  
0  
50  
100  
150  
2009 2010 2011 2012  
General Illumination Rest of Mass Market  
Source: iSuppli

---



SmartGrid:  
Stimulus and Innovation Driving Growth  
L t t h i B d  
ST: top 5 supplier  
t t t  
SmartGrid  
\$90M  
~\$3.4B in stimulus  
funding will drive  
>20% growth\*  
Largest growth  
opportunity in  
ZigBee/PLC/WiFi  
nodes  
ST is a Board  
member of ZigBee  
and HomePlug  
Alliances  
to US smart meter  
OEMs & 1st  
supplier of  
sensing  
technology  
Network Security  
& Encryption  
ST Americas:  
2012 potential new  
business target  
J2293  
Smart Meter  
PHEV  
Charging Source: ABI

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Smart Meter Solutions & Deployment  
Country (Utility) Customers (deployment)  
Italy (Enel) - ST7538/40 PLM-based meters 27M (complete)  
US (SCE, Duke, SDG&E, AEP, PG&E, FPL, etc) 40M (2015), 70M total  
China 200M (2015)  
M i (IUSA) STM32/STPM01b d 3 5M (2009) 4M (2010) 20M t t l  
SPEAR  
STM32  
StarGrid PLC  
Mexico - STPM01-based 3.5M (2009), 2010), total  
Spain (Endesa, Iberdrola) - ST7570/90-based 22M (2015)  
Brazil (ELO) - Echelon PLM-based 60M (2021)  
France (ERDF) - ST7570-based 35M (2015)  
Model BOM (\$) Features  
Low End 5 Manual read  
Mid R 10 AMR (1 )  
STM8S  
Power Management  
Metering  
STM32W ZigBee  
Display  
Current Sensing  
Voltage Sensing  
STPMxx  
SPEAR /  
Range 1-way)  
High End >15 AMI / IP Interactive  
Energy Management Power Line  
Modems  
ST75xx  
StarGrid SoC  
PRIME  
Real Time Clock  
+ Temp Sensor  
STPMxx STM32  
or  
STM8  
ZigBee  
STM32W  
Power Management  
VIPerXX / LXXXX  
22

Healthcare: e-Health/Remote Monitoring  
Consumer home New markets:  
di  
Engaged with top  
i l t bl  
Healthcare  
\$130M  
health & remote  
patient monitoring  
driven by insurance  
reimbursements  
cardiac  
monitoring, drug  
delivery &  
portable  
ultrasound  
Major MCU design  
wins in Home  
Health Care  
implantable  
device OEM &  
diabetes  
management  
leaders  
Bluetooth  
DUN  
GPRS  
Internet  
Care  
Server  
Band-aid or  
T-Shirt  
ST Americas:  
2012 potential new  
business target  
Internet  
ADSL  
User IP Box Doctor/User PC  
Off-body  
sensors  
Bluetooth  
Bluetooth  
SPP  
23

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Embedded MCU  
Broad portfolio  
of processor  
cores  
EnergyLite (TM)  
MCUs  
State-of-the-art  
process  
technologies  
Wireless and  
RF  
Key growth segments: energy management, healthcare & consumer  
STm32/8/Spear \$275M  
MCU (US\$M)  
p ST Americas:  
2012 potential new  
business target  
ST  
doubling  
MCU  
share  
24

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Brand Protection Solutions:

Counterfeiting, a Growing Financial Loss

Secure

Microcontrollers

Secure O/S

Development

State-of-the-art

process

technologies

Key

Management

Key growth segments: Computer Peripherals, Accessories and Medical

\$100M

ST Americas:

2012 potential new

business target

25

Sense & Power Strategy Outlook

High

Voltage

Switches

Power

Management

SoC for

Battery Packs

Connectivity

Innovative Audio

Amplifiers with

embedded

CODEC

Application

Specific Data

Converters

Growth across multiple segments: Computer, Consumer, Communication & Healthcare  
\$60M

ST Americas:

2012 potential new

business target

26

Americas:  
Distribution

---

Customer Reach

- o North American Distribution network: 90% of the market
- o 3 global distributors
- o Merchant Distributors: 15,000 customers
- o Catalog Distributors: 60,000 customers
- o ST is #2 broad-line supplier in NA

ST Sales Growth vs. Market

Distribution

broad o Sales Growth

- o #6 ranking in Q110
  - o +80% growth of sales to Distributors over 2009
  - o Profitability
  - o Systematic price increases accelerating margin growth
  - o New Product Design in
  - o #1 in Sales and Design in of ARM 32bit
  - o 70% Growth in Power MOS
  - o +100% Growth in High Reliability/Space
- 2009 2010 2011

ST Market

ST Market

New

Markets

Alternative

energy Lighting

Asset

tracking &

navigation

Medical >\$50M in

2010

- o New Market Penetration

Source: Lively Report, Shared Market Data

28



Key Takeaways

- o Increasing Demand Creation
  - o Reshaping the team, adding more local design
  - o Defining new products for the local market
  - o New Products
  - o New generation of MCU's
  - o Advanced digital and analog ASIC's
  - o New generation of MEMS
  - o Connected platforms (WiFi, MoCA, PLM) like 7108M and SPEAr
  - o Brand protection secure micros
  - o New Markets and Applications
  - o Smart energy
  - o Cloud computing
  - o Healthcare
  - o Internet-based devices
  - o Gadgets & gaming
-

Automotive Products Group  
Paul Grimme  
General Manager, Automotive Products Group (APG)

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Automotive Inside ST

ST Q1 2010 sales

100% = US\$2.325B

14%

12%

12%

8%

35%

19%

2

\* Sales recorded by ST-Ericsson and consolidated by ST are included in Communications and Distribution

Automotive Computer

Consumer Industrial & Other

Communications\* Distribution\*

ST: #3 in Global Automotive IC's  
ASIC-ASSP, MCU, MPU, VIPower, RF, Vision Sensors, DSP  
Products  
Power Train  
Engine Transmission  
Door Modules,  
Anti-theft  
Lighting,  
Wipers  
Body  
Electronics  
HVAC,  
Cluster  
Chassis-Safety  
Braking  
Steering  
Airbag  
Infotainment  
Car  
Infotainment  
PND  
Telematics  
GPS  
Customers Applications Segments

---

Automotive Competitive Environment

o Inside its specific perimeter, APG became WW leader in 2009

Rank Company

- 1 Infineon
- 2 Freescale
- 3 ST

Rank Company

- 1 ST
- 2 Freescale

Restricting to 3 Infineon

Ranking

General Stability

- 4 NEC
- 5 Renesas
- 4 Renesas
- 5 NEC

power +

analog +

digital

Competition

o Common enablers for leadership

Technology

+ Products

BCD, VIPower

ASIC portfolio

MCU roadmap

Infotainment

Strategy Innovation

Partnerships

4

- o Broad range offer
- o Quality and relationships
- o ST is recognized as having a strong, wide range network of Tier-1 customer

Car Market: After the Crisis

WW Data

o 2009 consumption was strongly incentivized by the world's governments

4.3%

5.7%

-4.2%

-13.0%

9%

7%

4.7%

55

60

65

70

75

80

Excluding China,

production dropped 20%

o Production fluctuation was much bigger than that of sales

o Positive signals now seen

o Very positive Q1 pace in NAFTA and Asia

o Platform developments restarted

50

2005 2006 2007 2008 2009 2010 2011 2012 2013

5

o Developing countries are growing faster than EU and developed Asia

Source: Global Insight

Automotive Market Growth Factors

More Cars, More Electronics

CAGR 2009-2016:

Cars: 6.2%

Electronics: 8.5%

250 Silicon: 10.2%

270

283

298

311 319 325 333

20000

25000

30000

35000

arket (M\$)

ASIC-ASSP

MCU

Power

Sensors

Electronic ignition

Electronic gearbox

Air conditioning

Antilock brakes

Navigation

Adaptive cruise ctrl

Airbags

Stability control

Night vision

Telematics

Bluetooth

Start/stop

Pedestrian detection

Lane change

Driver assist maps

Car 2 car

Internet

Brake-by-wire

Steer-by-0

5000

10000

15000

2009 2010 2011 2012 2013 2014 2015 2016

Silicon Ma

Standard

Others

Silicon/Car (\$)

1975 1985 1995 2005 2015

Central locking

Car radio

Seat heating

Automatic mirror

Xenon light

Hybrids

LED lighting

Steer by wire

Electric vehicles

25M cars 32M cars 36M cars 64M cars 86M cars

Source: Strategy Analytics

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2010-2015 - Macro-trends in Automotive

Innovation fueled

by social

A Global, Cost-

Driven Market

responsibility

Saving energy, saving lives

New automotive concept, fast

moving markets for cars &

electronics

Innovate

Car electrification

The safe and connected car

Simplify, Speed

up

The Small Car

The Low Cost Car

A Global Supply Chain

7

Future winners shall be leaders of both processes

Join innovation eco-systems, Manage new market dynamics and standards

2010-2015 - Macro-trends in Automotive

Innovation fueled

by social

responsibility

Saving energy, saving lives

Innovate

Car electrification

The safe and connected car

8

Leveraging partnerships with the industry leaders

Co-development as a model matching technology with know how

Strategy

- o Build on our strong positions via partnerships
- o Complete a full range of system components

Electric Power

Steering

Electric oil,  
water, fuel  
pumps

Electric

Parking

Brake

Green Car

Innovation Fueled by Social Responsibility

ST Response: Technologies

Product

- o Technology portfolio as first enabler
- o Market position: ASIC, vision processing, GPS
- o Tech portfolio: MCU, power, camera, RF, sensors
- o Partnerships: global leaders (Tier 1 and OEM)
- o Key Actions
- o Partnership with key IP companies

Smart battery  
charging

Engine

start-stop

Control

Pedestrian Detection

Safe Car

- o Electrification / safety joint programs
- o Government funded projects

Connected Car

9

Innovation Fueled by Social Responsibility

ST Response: A Test Case

Application: stability  
control for Japan

o Target is to allow an  
optimized ESC for all car

ST strategy: win with  
innovation

o Silicon technology: BCD8,  
0.18um, copper metalization

Result: a first silicon  
success

o Joint development team  
p with customer

segments

o Super-integrated IC with  
power (>5W) + logic  
(>100K gates)

o Tough requirements on  
performance, price, timing  
pp

o Package: HiQuad110(TM),  
copper wires, life guaranteed  
@175(degree)AEC

o Re-use of consolidated,  
successful architectures

o First silicon fully  
functional, able to run  
winter test in Q110

o Over \$100M lifetime value

2010-2015 - Macro-trends in Automotive

A Global, costdriven  
market

New automotive concept,  
fast moving markets for  
cars and electronics

Simplify, speed up

The small car

The low-cost car

A global supply chain

11

Adapting to the "new" world of Automotive

Different support needs, cost positions, geographies

A Global, Cost-Driven Market  
ST Response: Ease Of Use For Cost, Time to Market  
o Strategy  
o Engineer the portfolio to decrease system cost/complexity  
o ST advantages and actions  
Integration  
Systems-inpackage  
Systems-on-chip  
sense + power  
o Strong partnership with market leaders  
o Unique and strong ASIC history  
o Action: local development in geographies where growth is occurring  
o Strategy  
o Support market newcomers with standard low time to  
Full Solutions  
Systems on Target to grow  
WW leadership in  
airbag and small  
MCU engine control  
power  
peripherals  
solutions to allow fast and low-risk time-to-market  
o ST advantages and actions  
o Unique ASSP portfolio covering all segments  
o System understanding of basic applications  
o Action: engineering and starter kits  
Full IC kit  
HW + SW  
support  
Target to grow  
leadership in  
BRIC engine  
control

---

A Global, Cost-Driven Market  
ST Response: A Test Case  
Year 2005: start of  
new partnership  
o Target: engine control for  
Chi 4 li d  
Year 2007: new  
system ready  
o Production begins  
Year 2009: reached 60%  
of internal market share  
o ECU is present on  
China 4-cylinder car successful Chinese vehicles  
o Fully Chinese system  
development team  
o Requests to ST: support,  
speed, value  
o ST provided all  
semiconductors, plus SW /  
HW support  
o Joint technical team coworked  
for two years  
o Solution proved to be  
competitive in other regions  
2 14  
31  
58  
65  
Revenues (M\$)  
2007 2008 2009 2010 2011  
13

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APG - Main Growth Drivers & Expectations

- o Above market growth
- o Smart Power technologies will continue to be a main driver

Growth by Technology Family

MPU

32BIT MCU

- o Digital products add growth
- o MCU
- o MPU (ADAS, Infotainment)

o New market enablers are now being added to APG traditional portfolio

2009 2010 2011 2012 2013 2014 2015

- o In the future, further leverage in new technologies is planned
- o PMOS, IGBT
- o Sensors

14



Automotive electronics will be a continuing growth market, driven by vehicle demand and content per vehicle

Closing Comments

- o The market crisis in 2009 did not change the fundamentals, however it accelerated existing trends
- o Innovation and ease of use solutions will be critical components of growth for automotive electronics
- o The global supply chain is being re-shaped by shifting tastes and geographic locations of consumers
- o ST is among the few companies having all assets in place to turn this changing period into one of decisive growth

15

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Digital and Analog ASICs  
Gian Luca Bertino  
General Manager,  
Computer and Communication Infrastructure Product Group (CCI)

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Leader in Digital and Analog ASIC  
CARTRIDGE HDD PRINTER NETWORK  
Motor  
Controller  
Digital  
ASIC  
BS RF &  
Active  
Print  
Heads  
& Head  
Drivers  
BCD  
& SOC  
HCMOS  
Cables  
Drivers  
MFLD BICMOS  
TOP 1 TOP 2 TOP 3 TOP 3  
2

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Market Trends and Strategy in ASIC

- o Cloud computing will fuel the next wave, generating increasing demand for (green) infrastructure and transforming all applications in cloud conscious clients
  - o ASIC continues to be an effective win win model for CCI customers and ST Cloud Computing Web Connected Internet Traffic Green Systems win-continues to be committed to it
  - o The strategy: expanded product offering and flexible business model
-

CCI Performance Through the Crisis

80

100

120

100

200

60

Q407 Q409

Revenues (relative to Q407)

0

Q407 Q409

Operating Profit (rel to Q407)

100

105

110

60

80

Q407 Q409

HDD Revenues (rel to Q407)

95

100

Q407 Q409

Other Revenues (rel to Q407)

Leading by Technology Acceleration  
System-On-Chip

40%

60%

80%

100%

32nm

40nm

55nm

65nm

60%

70%

80%

90%

100%

BCD8 18

0%

20%

2007 2008 2009 2010 2011

90nm

110nm

>=130nm

0%

10%

20%

30%

40%

50%

2007 2008 2009 2010 2011

..18u

BCD6 .35u

BCD5 .50u

5

CCI Growth Drivers  
BiCmos ASIC  
for AOC and RF  
PrintHeads for  
InkJet Printers  
Digital ASIC for  
Networking  
Printer SOC and  
SPEAr eMPU  
6

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BiCmos ASICs for Networking

- o Leveraging best-in-class

BiCmos technologies from

ST technology portfolio

140

- o BiCmos7RF: State-of- the- art performances for both noise and linearity

- o BiCmos9MW: 100G Ethernet

Optical Link successfully demonstrated

- o Consolidating ST presence

80

100

120

in RF COTs for application

in wireless base-stations

- o Growing in the area of active cables

60

Q407 Q409

Revenues (Rel to Q407)

7



PrintHeads for InkJet Printers

140

160 o Expanding ST leadership  
in thermal printheads

o Best-in-class microfluidic

80

100

120

Best in technology

o Strategic partnerships  
with multiple customers

o Revenue growth very  
material in 2009

60

Q407 Q409

Revenues (Rel to Q407)

o Investing in Piezo  
technology to address  
new markets

8

Digital ASIC for Networking  
100 o Enterprise market slower  
than consumer to go back  
to pre-crisis

70

80

90

o Anticipating strong growth  
from 2010 onwards,  
fueled by multiple wins in  
65nm reaching production

o Launching 32LPH, first  
32nm bulk process for  
networking applications

60

Q407 Q409

Revenues (Rel to Q407)

g pp

o Launching S12, first  
12.5GBit/sec SerDes in  
32nm bulk process

9

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STMicroelectronics Announces 32nm Design Platform for Next-Generation System-on-Chip ICs for Networking Applications

Geneva, May 25, 2010 - STMicroelectronics (NYSE: STM), a world leader in high-performance System-on-Chip (SoC) ICs, today announced full availability of a 32-nanometer (nm) technology platform for the design and development of leading-edge application-specific integrated circuits (ASICs) for networking applications. Central to the new 32nm SoC design platform, which implements ST's 32LPH (Low-Power High-performance) process technology, is the industry's first Serializer-Deserializer (SerDes) IP available in 32nm 'bulk' silicon. Enabling very large ASIC designs, greater than 200mm<sup>2</sup>, ST's new 32nm 32LPH ASIC design platform enables an unprecedented mix of high performance, high complexity, low power consumption and reduced silicon real estate per functional block. The platform is designed to accelerate the development of next-generation ST's Next Generation Platform

generation networking ASICs used in high-performance applications such as enterprise switches, routers and servers as well as optical cross-connect and wireless infrastructure applications.

"With the introduction of the 32LPH platform, ST is enabling the next generation of equipment for communication infrastructure applications, which requires highly integrated ASICs that can satisfy the increasing demand in performance, while also meeting extremely challenging power consumption and silicon integration goals," said Riccardo Ferrari, Group Vice President and General Manager of ST's Network and Storage Division. "We are extremely encouraged by the strong interest that customers are demonstrating for this platform, which has already gained key design wins."

ST's SerDes IP, called S12, is a key piece of intellectual property that has already been successfully demonstrated in labs at selected key customers. The S12 IP is vital for the development of ASICs for networking applications and enables chip-to-chip, chip-to-module and backplane communications in networking equipment designs.

"ST is the first silicon supplier to bring a full design platform in a 32nm bulk-silicon process technology to the communication infrastructure market, including a next-generation predictive ASIC top-down design methodology, together with a full set of proven IP blocks such as a SerDes and embedded DRAM, successfully developed over many years by ST in previous technology nodes," said Philippe Magarshack, Technology & IP R&D Group Vice-President, Central CAD & Design Solutions GM, STMicroelectronics. "ST's Technology R&D center in Crolles, France, has been instrumental in accelerating the completion of the 32LPH platform where low-power technology meets the high-performance requirements of networking applications, while still enjoying all the cost benefits of high-volume manufacturing. In addition, we have partnered with selected EDA vendors to offer networking customers the benefits of a predictable ASIC turnaround time, including fast virtual physical prototyping, and 32nm-class timing, signal and power integrity sign-off."

The first ASIC prototypes implemented in ST's 32LPH process technology are expected early in 2011 production ramp-up in the second half of 2011.

Further Technical Information

ST's 32LPH (Low-Power High-performance) design platform for networking applications supports up to 10 metallization layers to increase routing efficiency. The platform is based on the 32nm High-K Metal Gate process developed within the framework of the ISD alliance, but also incorporates specific IP and devices from ST, such as embedded DRAM with 10-Mbit per square millimeter density and Ternary Content Addressable Memory (TCAM).

10



Printer SOC and SPEAr

140

160 o SPEAr family now expanding  
with the launch of the 1300  
series

80

100

120

o Enabling flexible ASIC models  
into multiple applications

o Decreasing cost of ownership  
to customers

o State-of-the-art SOC  
architecture

o Anticipating continuous growth  
i f d f l d b

60

Q407 Q409

Revenues (Rel to Q407)

moving forward fueled by  
recent wins in printer SOCs  
and increasing revnues from  
the SPEAr family

11

SPEAr Enables Multiple Business Models

Traditional

ASIC

Flexible

ASIC

Embedded

Processing

MCU

eMPU

ASIC

STM32

STM8

SPEAr

SPEAr (TM)

Flash, SRAM

SDRAM, DDR

LEDs,

KBD,

LVDS

Customizable

Logic Gates

Memory

Cards

Decreasing Cost of Ownership to Customers

12

STMicroelectronics Expands its SPEAr(R) Microprocessor Family for High-Performance Applications  
New advanced symmetrical multiprocessor architecture from ST delivers cost efficiency, computing, and customizability for multiple embedded applications  
Geneva, May 27, 2010 - STMicroelectronics (NYSE: STM), a world leader in system-on-chip technology today revealed the new architecture that will be the backbone for the new members of its popular SPEAr(R) (Structured Processor Enhanced Architecture) family of embedded microprocessors, targeting high-performance connectivity and embedded applications.

Leveraging its experience of the production-proven SPEAr300 and SPEAr600 lines, the new SPEAr1300 product line couples powerful dual ARM Cortex-A9 processors with a DDR3 memory interface and is manufactured in ST's low-power 55nm HCMOS (high-speed CMOS) process technology. The dual ARM Cortex-A9 processors support fully symmetrical operation, at speeds up to 600MHz/core for 3000 DMIPS equivalent.

#### Expansion of SPEAr Family

The SPEAr1300 makes use of ST's innovative Network-on-Chip technology for internal peripheral interconnect, assuring support for multiple different traffic profiles, while maximizing data throughput in the most cost-effective and power-efficient way. Initial sampling has already started to early adopters.

The new architecture offers industry-leading performance in terms of DMIPS/MHz and power consumption/DMIPS ratios, in addition to cost efficiency and customizability advantages. The availability of integrated DDR3 memory controller and a full set of connectivity peripherals like PCIe, SATA, USB and Ethernet, among other features, make the SPEAr1300 the ideal choice for high-performance applications including networking, thin client, videoconferencing, NAS (Network-Attached Storage), computer peripherals, and factory automation.

"This new architecture for the SPEAr family builds upon the unrivalled low power and multiprocessor capabilities of the ARM Cortex-A9 processor core" said Loris Valenti, General Manager of ST's Computer Systems SoC Division. "Upcoming SPEAr embedded microprocessors will deliver an unprecedented combination of processing performance, memory throughput, flexibility and low power for next-generation connectivity appliances."

Key features of the new SPEAr1300 architecture include:

- o Dual ARM Cortex-A9 cores, running at 600MHz for 3000 DMIPS equivalent
- o 64-bit AXI (AMBA3) bus Network-on-Chip technology
- o DRAM and L2 cache with Error Correction Code (ECC)
- o 533MHz 32-bit DDR3 memory controllers with ECC; 16-bit DDR2 also supported
- o Accelerator coherence port
- o Gigabit Ethernet
- o PCIe 2.0 supporting 5 GT/s (Gigatransfers/second)
- o SATA II 3 Gbit/s
- o USB 2.0
- o 256-bit key hardware encryption/decryption
- o 1.3 million gates of configurable logic

Embedded microprocessors from the new SPEAr1300 product line will be announced over the next few months, expanding ST's SPEAr family and providing an extensive choice for leading customers.

Further information on ST's SPEAr family of embedded microprocessor System-on-Chip ICs is available at [www.st.com/spear](http://www.st.com/spear)

SPEAr Roadmap  
2A9-1300  
1300k gates  
Dual Cortex-A9  
600(1)MHz  
HD Display, 3x PCIe  
55 HCMOS LP  
SPEAr1300  
General Purpose  
External AMBA bus  
Flexible ASIC  
Off the shelf eMPU  
SPEAr300  
VoiP, Security  
SPEAr600 55nm General Purpose  
External AMBA bus  
2H9-600  
600k gates  
Dual ARM926  
333(1)MHz  
XGA display controller  
90nm HCMOS GP  
SPEAr 1300  
First eMPU with  
SPEAr1310  
Communication  
SPEAr320  
Automation  
SPEAr310  
Communication  
H9-300  
300k gates  
ARM926  
333(1)MHz  
65nm HCMOS LP  
Dual Cortex A9  
available in silicon  
14

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Addressing Multiple Applications

Bar Code

Automation

Thin Client

Networking

Instrumentation

VoIP

Imaging

Access Point

e-book

Docking Station

15

Key Takeaways

- o CCI product group is delivering solid results
- o Revenues in excess of \$1B
- o Operating margin in the low double-digit range
- o CCI product strategy centered on traditional ASIC, flexible ASIC and eMPU
- o Strategy to grow in Analog
- o Continue to be a market leader in motor controllers for HDD and printers, and in printheads for inkjet printers
- o Now accelerating BiCmos ASICs for both active optical cables and RF interfaces
- o Strategy to grow in Digital
- o Significant design wins in the areas of communication infrastructure and printers
- o Launch of the first 32nm bulk platform for networking applications
- o Expansion of the SPEAr family with the launch of the 1300 series
- o Tactical participation in HDD SOC

16

Home Entertainment & Displays  
High on Entertainment - Low on Power  
Philippe Lambinet  
General Manager, Home Entertainment & Displays Group (HED)

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HED Driving Multimedia Convergence  
Set-top boxes  
TVs / Monitors Audio  
Sensors  
2

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Consumer Electronic Trends

- o Analog switch-off
- o Increasing demand for Pay TV and FTA satellite
- o New connected services
- o Content aggregation - broadcast & IP
- o Services across all consumer devices
- o Exciting entertainment experience
- o 3D stereoscopic TV
- o GUI technologies -- 3D graphics, MEMS...
- o LED BLU
- o Environmental factors
- o Power consumption
- o Green production

3

---

STB Market

- o New value-added services in EU and USA
- o Broadband & broadcast
- o Monetized with advanced security

Mu

Terrestrial

50

100

150

- o Combined with home networking
- o China market is the largest market with growth in cable & IP

o Brasil India Satellite

IP

0

2009 2010 2011 2012 2013 2014

Brasil, India, deploying on SD

H.264 essentially starting to commoditize

- o MPEG2 commoditization
-

DTV Market

- o Larger share of screen size for 40" and above

Mu

50

100

150

200

- o More internet services & content targeting connected TV

- o Faster migration rate to digital reception

- o Fast technology pace

LCD

Plasma

0

2009 2010 2011 2012 2013 2014

gy p

- o 120Hz to 240Hz

- o LED BLU

- o 3DTV

Source: iSuppli

DTV Market

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Our Application-Platform Evolution

Gen. 1 Gen. 2 Gen. 3 Gen. 4

Fully open  
connected

New services

New UI

Best

Performance/

HD H.264

market

platform

internet TV

enabler cost ratio Client/server

STi7100

STi7103/FLI106xx

STi7105

STi7104/FLI326xxH

STi7108

FLI7510

7109, 5202 7111, 7141, 7200

5211, 5206, ...

71xx, 52xx

STi7xxx

FLi7xxx

MPEG2 1000 DMIPS CPU Dual CPU & L2 cache Multi-core SMP CPU

Mass production Mass production In design

Production: 2007 a(3) Production: 2009 a(3) Production: 2010 a(3) Production: 2011 a(3)

Samples now

>5000DMIPS

Introduction of:

Dual 1080p60 decode

HD encode

Display Port, MOCA 2

>2000 DMIPS

Introduction of:

1080p60 decode

3D GL-ES2.0

MOCA 1.x

Introduction of:

AVS HD

DDR2

e-SATA

6



HED H1 2010 Highlights

- o G2 based STB massively deploying
- o Mass production started in June 2009
- o 55nm process with >10 products families
- o > 50 customers now in production
- o > 50% of ST total STB shipments from 2010
- o G3 getting ready for ramp up in 2010
- o G3 introduced at CES 2010 in January 2010
- o Freeman/FLI7150 solution for DTV designed in at multiple partners
- o >20 partners enabled with STi7108 platform
- o Develop new category of STB & media center
- o Develop new software for new services
- o RIA, GUI, gaming, mediaserver, ...

7

---

ST Vision  
o Merging broadcast and internet TV  
Client/server  
Open internet  
o Graphics  
o Video/audio quality  
o New  
Services User  
Experience  
Green  
o Low-power  
o Sustainable excellence  
Gaming  
o Remote control  
8

---

Why Reduce Power in CE ICs?

- o Governmental regulations compliance
  - o End customer demand: a consumer selection criteria
  - o Optimized product cost
  - o Bill of material
  - o Product reliability
  - o ST vision: ST's environmental engagement to sustainable excellence
- 9
-

Principles for Sustainable Excellence

Energy

Electricity consumption per unit of  
production - normalized values

100 KWh/production unit

Target

Water

Water consumption per unit of  
production - normalized values

100 m3/production unit

Target

CO(2) emissions

Absolute values Reduction of waste

3500 Total

T t E

0

50

1994

1995

1996

1997

1998

1999

2000

2001

2002

2003

2004

2005

2006

2007

2008

0

50

1994

1995

1996

1997

1998

1999

2000

2001

2002

2003

2004

2005

2006

2007

2008

-500

500

1500

2500 1994

1995

1996

1997

1998

1999

2000

2001

2002

2003

2004

2005

2006

2007

2008

Tot. Energy

PFC

Sequestration

Transportation

Landfill: from 71% in 1994 to 4% in 2008

10

Processing Performance Evolution

5000

6000

MIPS

x14

1000

2000

3000

4000

0

G1 G2 G3 G4

> 240% performance increase over 3 product generations

11

STB Security Requirement Evolution

2010

Broadcast TV services Broadcast & broadband multimedia services

o New value-added services require increasing security resilience

Broadcast

VOD

Broadcast

TV

Gaming

(GOD)

eBanking

eGovernment

eHealth

Application

Store

Broadband

TV, VOD

....

o Rapidly increasing service choices accessible by users requires increased security flexibility without compromise on robustness

ST's Strength in CA & Security

- o Long-time partnerships with leading security vendors and more
  - o Mastering security from end-to-end
  - o Security technology developed internally allows for faster adaptation as security evolves
  - o Full support for smartcard and internal CA
  - o Late security customization in manufacturing flow
  - o Delivery flexibility and reduced inventory
- 13
-



Audio & Image Quality Enhancement

- o Leveraging years of excellence
- o Internet-driven content requires extensive video processing to meet customer's quality expectations
- o Sound terminal for high quality low cost speakers

14

ST is Ready for 3DTV

- o Deployable now!
- o Side-by-side support (SbS)
- o Top-and-bottom support (TaB) L

R

- o 1/2 resolution 1080p
- o Available on all G1 & G2 platforms
- o Ready for the future
- o Frame sequential support added
- o Full HD resolution

L R

R

- o Frame rates increasing
- o 60fps on G3 platforms
- o 120fps on G4 platforms

3D Graphics on G3 and G4

3D

polygons High definition

Video

texturing

Procedural

texturing

resolution

Fast redraw

- o Standards-based: OpenGL-ES 2.0 and OpenVG 1.1

- o Optimized for new class of user interfaces

- o Paves the way for gaming services

16

Summary

- o ST has an established position in the home entertainment market
- o OEM, Ecosystem familiar with ST
- o Proven solutions
- o ST provides complete solutions for a wide range of consumer services:
- o STB, DTV and other CE devices
- o Unmatched user experience, services and energy-efficiency
- o ST deploys new technologies for home entertainment to grow revenue
- o 3D video, 3D graphics, image quality, ...
- o Compelling internet convergence
- o Casual and full gaming ...
- o ST helps build greener products

17

Microcontrollers, Memories,  
Secure Solutions  
Claude Dardanne  
General Manager, Microcontrollers, Memories & Secure Solutions Group (MMS)

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MMS at a Glance

- o EEPROM memories

- o #1 Worldwide supplier

MMS 2009 Business by Activities

- o 31% share Q409\*

- o Microcontrollers

- o #8 Worldwide supplier

- o 5.8% share 2009\*

- o # 3 Secure MCUs

2

- o # 8 GP MCUs

MCU TAM CAGR 2010-14\*

+6.4%

a(3) Key opportunity for growth

Source: iSuppli & WSTS

---

MCUs Market Drivers

- o General Purpose MCUs
- o Industrial market
- o Energy management: metering...
- o Consumer: user interface

MCU Worldwide TAM\*

US\$B

interface...

- o Healthcare: glucose meter...
- o Automotive: car body, safety...
- o Secure MCUs
- o Smartcards: SIM...
- o Pay TV
- o Brand protection

3

- o IT: Trusted platform...

- o Dedicated Automotive MCUs

(Focus from ST dedicated Automotive Products Group)

Source: WSTS

Dynamics a(3) General Purpose MCUs

- o \$8B business opportunity in 2011
- o Multi-segments market
- o Steady growth foreseen in the next 5 years
- o Well established and profitable business model
- o Migration to 32bit CPU based on advanced e-NVM technology
- o Customers
- o Tens of thousands of customers worldwide
- o Broad, multi-applications and fragmented business
- o Customer investment in software ensures higher business

4

g

stability and strong commitment to a family of products

- o Complementary to ST's advanced analog portfolio
-



Dynamics a(3) Secure MCUs

- o \$2B business opportunity in 2011
  - o Smartcard applications driven (SIM, Banking, Government, ID, Transport)
  - o Global shift to digital electronics requires more and more embedded security functions
  - o Migration to Flash based e-NVM technology embedding advanced security features
  - o Customers
  - o In addition to key Smartcard suppliers, other customers are recognizing the value of embedded security functions
  - 5
  - o Strong commitment to a family of products due to software investment, better business stability
  - o Technology driver for microcontrollers products
-

MCUs Shared Platforms

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Shared Platforms Key Features

- o State-of-the-art embedded NVM technologies
  - o e-Flash
  - o E-EEPROM
  - o High-performance CPU cores
  - o 8-bit
  - o 32-bit
  - 7
  - o System know-how
  - o General purpose
  - o Security
-

State-of-the-Art e-NVM Technology

2008-09 2010-11 2012-13

e-Flash 90nm 80nm 55nm

e-EEPROM 130nm 90nm

8

a(3) High speed

a(3) Ultra low power

a(3) Advanced Analog functions

High Performance CPU Platforms  
Computing  
Power  
32-bit ARM Cortex  
5 stages pipeline  
under evaluation  
32-bit  
32-bit  
Light  
32-bit SC000  
Secure-M0  
32-bit SC300  
Secure-M3  
ST33  
32-bit  
Cortex-M3  
STM32  
High-End  
Cortex - M4  
32-bit  
ARM Cortex  
Family  
9  
2008-2009 2010-2011 2012-2013  
8-bit  
Proprietary  
Secure  
STM8

---

From Enablers to Markets  
Memories  
General Purpose  
Applications  
Microcontrollers  
General Purpose  
Applications  
Security  
Specific applications  
IP Portfolio  
RF  
Embedded Software  
RF  
EEPROM Memory Array  
Dedicated blocks Dedicated blocks  
Touch RF  
sensing  
Dedicated blocks  
General Purpose &  
Advanced Analog  
Embedded software  
Cryptography &  
Secure Peripherals  
10  
Enablers  
Advanced CPU  
(8 & 32-bit Platforms) Pure EEPROM Technology  
e-NVM Technology (Standard and Low Power)

---

From Societal Needs to Solutions

Integrated Controllers

- o Ultra-low-power
- o A/D converter

Energy

efficiency

System & product know-how Needs Solutions

- o Smart metering
- o Appliance control
- o Sensors network
- o Home monitoring
- o Therapy control
- o Drug traceability
- o Pay TV, touch control
- o Brand protection
- o Connectivity

Secured solutions

- o Trusted processing
- o Tamper resistance
- o Cryptography

Aging &

Health care

Communication/

Entertainment

11

- o M2M, NFC & SIM
- o Fare collection
- o e-Passport
- o Real-time monitoring

MMS Growth Strategy

---



ST's Microcontrollers Key Strengths

- o General purpose MCU strengths
- o Leadership position on the 32-bit market based on STM32 (ARM Cortex) platform
- o Advanced e-NVM roadmap (ultra-low-power & RF focus)
- o Advanced Analog capabilities
- o Secure MCU strengths
- o Market acceptance of ST23 & ST33 platforms
- o Advanced e-NVM roadmap

13

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- o Advanced security features know-how
  - o 20% market share with limited participation to the SIM market
-

New MCU Platforms Deployment

> 5x

> 10x

> 3x

14

General Purpose MCUs Secure MCUs

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MMS' Growth Strategy

- o General Purpose Microcontrollers
  - o Capitalize on solid market acceptance of the STM32 platform
  - o Broaden STM32 microcontrollers portfolio to ensure huge pervasion and improve market coverage
  - o 16-bit market coverage with ARM M0 32-bit light Cortex
  - o High end 32-bit market coverage with ARM M4
  - o Increase x5...x10 the number of customers using STM32 platform
  - o Secure Microcontrollers
  - o Expand ST23 & ST33 secure platforms to new applications
  - o Trusted computing...
  - o Maintain leadership position in advanced security features
  - 15
  - o EEPROM
  - o Long-term commitment to stand alone EEPROM products
  - o >2B units shipped per year, up to 2Mb density
  - o Create a new market standard with dual mode EEPROM (RF + contact)
-

MMS Product Highlights

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STM32 for Appliance (Motor) Control

ADC input

12-bit ADC

Main board or

dash board

Power

converter

- o Noise reduction

- o Key features in STM32

- o High-performance CPU

- o Embedded Flash memory

- o ADC, MC timer

PWM output

3-ph motor control

16-bit timer

Dual 12-bit DAC

H/W CRC for Flash

integrity check

Timer input

capture

Inverter

Motor

T

17

- o Control software libraries

- o Cost effective

- o Key Technologies for evolution: Advanced DSP, design optimization

STM32L for Health Applications  
Key features in STM32  
o High-performance CPU  
o Extended portfolio  
Test Strip  
Chemistry  
o Ultra-low-power STM32L  
Analog  
switches or  
sensor  
Power  
FSMC / SPI management  
SPI  
ADC 12-bit  
2x12-bit  
DAC  
2 x Opamps  
STM32  
256/512K  
FLASH  
SDIO/SPI NVM/E(2) PROM  
USB Connectivity  
RTC 32KHz  
Glucose Meter  
18  
a age e t  
Display  
OLED/TFT  
2/3 x AAA batteries  
Coin cell or  
Supercap in backup

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STM32W for Wireless Sensor Networks  
Rehabilitation,  
balance control  
Healthcare/  
assisted living  
Security  
Sh k ti th ft  
Sport & Wellness  
Sport monitoring  
"In-network" distributed computation  
Consumer control  
Games & remote  
Infrastructural  
monitoring  
Buildings, bridges  
Shock sensor, anti-theft,  
anti-intrusion  
monitoring,  
pedometer,  
fall detection  
Reduced data transmission  
Increased network lifetime  
19  
Industrial  
Vibration & tilt  
remote  
measurement  
Energy  
management  
Smart metering

---

STM32 for Smart Electricity Metering

L

Battery Display

N Backup

Power Line

MODEM

ANALOG to

DIGITAL

Voltage

& current

sensors

STM32

Up to 120MHz / 1MB Flash

Single or Multi

Phases

RF Security

Serial

- o Energy efficiency

- o Global trend to SmartGrid

- o Smart meter as central element

- o Key features in STM32

- o High performance CPU

- o 20

- o Key Technologies for evolution: Power line, RF connectivity, ADC, Tamper resistance

Future integration steps

ZigBee &

Sub GHz

Module NVM

(load profiles)

Low power & Real Time Clock

- o Embedded Flash memory

- o Extended portfolio



T33F1M for High-end Secure SIM Card

- o Pay with your SIM
- o Visa & Mastercard payment applications
- o Banking security level
- o Travel with your SIM
- o Mifare, Felica, Calypso applications
- o "Over The Air" reloading & management

21

- o Multimedia on your SIM
  - o Integrated webserver
  - o Enriched content & applications on the SIM
-

ST21NFCA & ST33F1M for NFC solutions  
o Bring contactless capability to a handset  
Reader Payment  
ST21NFCA  
Transport BT pairing  
ST33F1M  
22

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ST33ZP24 SoC for Trusted Platform

- o Leading-edge secure 32-bit CPU
- o State-of-the art 90nm e-EEPROM technology
- o Embedding in-house TPM Firmware
- o Supporting multiple hardware interfaces
- o LPC for PC platforms
- o SPI, I2C for embedded platforms

S Trusted Platform

PC

Mobile Smartphone

23

Main

Processor

TPM

Server

Copier

Router

ST23YR for Contactless Solutions

- o ST23YR designed for advanced security and highspeed contactless solutions

- o ST23YR80:

biometric passport transaction ( 3 seconds

- o ST23YR18:

EMV Paypass DDA transaction ( 300ms

24

- o ST23ZR08:

secure transport solution

AuKey Solution for Brand Protection

- o Turnkey solution based on highly secure operating system running on ST23 platform
- o AuKey to authenticate securely:
- o Printer cartridges
- o Game peripherals
- o Docking station
- o Network accessories

25

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Dual Interface Serial EEPROM

- o Application parameters are accessible from the inside (I(2)C) & the outside (RF) of electronic equipment

P i (ISO15693) RF i t f

M24LR64

- o Passive interface

I(2)C interface EEPROM RF interface o 32-bit password protection

Parameters such as settings, traceability, maintenance logs, firmware... can be read and updated:

- o Anywhere in the supply chain

- o At no on-board power cost

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p

- o During the entire product lifetime (manufacturing, shipping, maintenance ...)

- o Even when the device is turned off or in its shipping box

Allows extra flexibility for supply chain management

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Conclusion

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Microcontrollers Opportunities

- o General purpose microcontrollers market
  - o Very large and well established market
  - o Market migration to 32-bit well synchronized with STM32 platform introduction
  - o Early success of the STM32 ramp-up
  - o New business opportunities allow for increased market share
  - o Secure microcontrollers
  - o Electronics market moving to digital
  - o Early success of ST23 & ST33 ramp-up
- 28
-



MEMS & Advanced Analog  
Benedetto Vigna  
General Manager, MEMS, Sensors and High-Performance Analog Division

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MicroElectroMechanical Systems (MEMS)

- o MEMS take advantage of the electrical and mechanical properties of silicon
  - o Electronic circuits
  - o Mechanical structures
  - o Semiconductor manufacturing
  - o High volume
  - o Small size
  - o Low cost
- 2
-

Key Messages

- o Leadership in MEMS for consumer market
- o Extended customer base
- o Nimble product development
- o Timely investment in state-of-the-art manufacturing
- o In 2009, expanded accelerometer portfolio with
- o Gyroscopes, microphones, compasses
- o Smart sensors: iNEMO(TM)
- ....toward the "One-Stop MEMS Supplier" goal
- o Leverage leading MEMS position and strong competence to increase presence in advanced analog

3

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MEMS Leadership

ST is # 1 in MEMS for consumer electronics and mobile handset market

2009 ST revenues = \$218M; Market TAM = \$1,170M\*

ST leads accelerometer business in all market segments

Consumer electronics and mobile handsets\*

2009 ST Market Share = 50%

All markets, including automotive and industrial\*

2009 ST Market Share = 21%

4

\* Source: iSuppli

Manufactured > 750M

accelerometers and gyroscopes

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MEMS Motion Sensors

9.6% CAGR

US\$M US\$M

6%

CAGR

13%

CAGR

8%

CAGR

25%

CAGR

15.3% CAGR

Accelerometers Gyroscopes

Source - iSuppli

Consumer Markets Exceeding Automotive Markets in Units and Revenue

5

ST Drives MEMS Avalanche

o 2005:

We entered PCs

o 2006:

We entered Gaming

o 2007:

We entered Phones

6

2008:

We entered Pockets

ST Continues to Drive MEMS Avalanche

o 2009:

We entered Cameras

o 2010:

Source: iSuppli reverse analysis of Apple iPad

7

MEMS Enable New Applications  
L t i B d S i  
Point Of Interest  
Optical Image Stabilization  
Location Based Services  
Enhanced User Interface  
& On Line Gaming  
8  
Augmented Reality

---



MEMS for Optical Image Stabilization  
x  
Hand tremors cause blurred images  
Translation Rotation z  
z  
Rotation x Rotation y  
Gyroscope senses tremors and the  
micro-actuator compensates  
9  
OIS OFF OIS ON

---

MEMS and GPS Enable Location-Based Services  
How much is that shirt? POI POI Filtering  
Augmented Reality\*  
No compass With compass Point Of Interest  
Source: [www.apple.com](http://www.apple.com) (Wikitude)  
10

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MEMS in Automotive Market  
Navigators  
Anti-theft systems  
Crash recording  
Post-crash door unlock system  
Dangerous driving detection  
11  
.... and much more...

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MEMS in Healthcare

- o Sensing
- o Body motion
- o Pressure

A i i l Insulin

Flexible Lens for

Eye Pressure

Monitoring

Electro

Cardiogram

- o Acoustic signals
- o Bio signals (ECG, BGCM)
- o Biosensors
- o Drug Delivery

Movement

Recognition

Nano Pump Temperature

Sensor

Pressure

Sensor

12

- o Pumps
- o Valves
- o Nozzles

Step Counter

2009: Not Only Accelerometers.....  
13

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Cristallo:

Ultra-Low-Power and High Performance Accelerometer

Higher flexibility at lower current

Advanced power management

o Wide supply voltage down

to 1.8V

o Ultra low current

High versatility

o Extended FS range

(2/4/8/16g)

o Multiple configurable

interrupt sources

Embedded features

o Programmable FIFO (32

levels)

o 3 auxiliary ADC channels

14

100X Lower Power

Gyroscopes: We Are On Time

Analog Output

In 2009, we announced more than

30 Multi-axis Gyroscopes

2008

1X

2009

2X

Analog Output

15

E Jan 2010

3X

Analog and

Digital Output Gyroscopes market for mobile

and consumer TAM 2010:

\$246M CAGR 2010-2013: ~20%

Source: iSuppli

Application Segments:

- o Enhanced motion user interface
  - o Image stabilization
  - o Gaming
  - o Navigation
-

Pressure Sensors as Altimeters  
Absolute, temperature-compensated, ultra-compact  
pressure sensor with digital output  
... make it small; make it  
accessible

16

Pressure sensors market for mobile  
and consumer TAM 2010: \$47M

CAGR 2010-2013: ~27%

Source: iSuppli

Application Segments:

- o Blood pressure sensors
- o Navigation system
- o Water level m



Microphones Enhance User Experience

Your mobile phone becomes your conference-call solution

A l i t i S t

oExcellent sound quality

oSuperior reliability and robustness

17

Source: iSuppli

Microphone market for mobile and

consumer TAM 2010: \$176M

CAGR 2010-2013: ~24%

Application Segments:

o Mobile phone

o Digital camera/camcorder

o Laptop PC

o Gaming

Compass Shows Heading  
Accelerometer  
A look from the Inside... ...and from the Outside  
Geo-Magnetic Sensor  
+  
Application Segments:  
o Navigation  
o Mobile phone  
o Pictures geo-tagging  
o Location based services  
18

---

iNEMOTM : The Smart Sensor  
Smart sensor: combination of sensors, data processing  
and information transmission  
19

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What's Next in iNEMOTM family?  
3x accelerometer (LIS3DH)  
3 di it l  
6 axis integrated modules  
20  
3x accelerometer (LIS331DLH)  
2x P&R or P&Y gyroscope (analog)  
7.5x4.4 mm2

---

MEMS are Advanced Analog Products

- o MEMS means Micro Electro Mechanical Systems ... taking advantage of the mechanical AND electrical properties of silicon

- o Three key elements:

- o Micron-sized Transducer realized through a specific process called Micro-Machining (THELMA)

- o An Advanced Analog Chip with embedded smart functionalities

- o Dedicated package and calibration features

THELMA @ 1 um ASIC @ 130 nm 3 Axis Gyroscope

+ =

21

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MEMS are Advanced Analog Products

Supply Monitor Power Management

Audio Amplifier

A typical Analog Signal Chain

Amplifier

Analog to

Digital

Converter

Control

Unit

Digital to

Analog

Converter

Amplifier

RF

Interfaces

Logic

Interfaces

Sensor Actuator

Gyroscope

22

All available in Stand Alone, ASSP and ASIC products

Analog: an IMS Competitive Advantage  
Key product family Key Target Applications  
High End Analog Front  
End  
Healthcare, Industrial, Portable  
Devices  
Mixed Signal ICs Mobiles Peripherals Portable Medical  
Analog Ranking 2009  
Analog ICs\* # 2  
o Can integrate Analog and Power (chip or package) in Power Conversion and  
Power Management applications  
o System know-how to design dedicated ICs for complex applications  
Competitive Advantages:  
Mixed Mobiles, Peripherals, Low Voltage  
Operational Amplifiers  
Mobiles, PDAs, e-Books  
\*Ranking refers to total ST Analog ICs sales  
23  
Y g p pp  
o Variety of reference designs for medium and small customers  
o Delivery of System Solutions including Sensors, Analog ICs, Microcontrollers  
and Power Discrete  
o The World's largest and most cost-effective 6" Front End in Singapore  
Source: iSuppli, ST

---

Sensors Complement ElectroCardioGraph

HM222R

2 Ch 1

Remote monitoring  
and telemetry

Channel +

Microcontroller +

Accelerometer + BTLE

HM221R

2 Channel +

Microcontroller+

accelerometer

HM301D

HMX11D

HMX11D+Isolation

HM101D

1 Channel

Diagnostic

ECG/EEG and AED

+ Bedside monitoring

24

HM201D

2 Channel



Smart Sensors:  
New High-Growth Opportunities  
Factory Logistics  
Building  
Healthcare  
Sport & Wellness  
g  
Automation  
25

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Sustaining Growth  
26

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Takeaway Messages

- o 2010 will be "Year of the Gyroscope"
- o ST will continue to drive MEMS avalanche and extend presence in new markets
- o ST investing heavily in MEMS and Advanced Analog products to sustain growth
- o ST well positioned to become undisputed leader in Smart Sensors, bridging analog world to digital brain
- o Sensors will enhance presence in the advanced analog world

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Power & Smart Power Solutions  
Matteo Lo Presti  
General Manager, IMS System Lab & Technical Marketing

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Key Topics

- o Power management in IMS today
  - o Vision and awareness
  - o Innovation in technologies and products
  - o System innovation
-

Power Discrete: Strong Market Position

Power Discrete Ranking 2009

Power MOSFET (High Voltage) # 1

Protection & IPAD # 1

Thyristors # 1

Key product family Key target applications

HV Power MOSFETs Power supply, lighting, solar

Rectifiers Power management

ACS switches Home appliances

o The widest range of power technologies and packages from low to very high voltage (MOSFET, IGBT, Bipolar, IPAD, Rectifiers) offering the highest efficiency in

Competitive Advantages:

Rectifiers & power diodes # 3

switches Protections & IPAD Mobiles, USB/HDMI

interfaces, wired data transfer

the most demanding applications

o Expertise in composite materials (SiC, GaN) for high frequency and very high

temperature applications (Electric Cars, Photovoltaic Converters, Wind Generators)

o Extremely competitive manufacturing machine (Singapore, Long Gang, Shenzhen )

3

Source: iSuppli, ST

Power Management ICs: Pillar of IMS

Key product family Key Target Applications

Off-line converter ICs Power supply, lighting

Mixed Signal ICs Mobiles, peripherals, portable

di l

Power Management\*

Ranking 2009

Power Management # 2

o Innovative System Solution combining Smart Power ICs, Power Discretes and Microcontrollers on a single board or in a single package

Mi d t h l i (di it l i l d l d hi h lt ) t d l

Competitive Advantages:

medical

Battery Management ICs Mobiles, PDAs, e-books

LED Driver ICs Street lighting, building, panel

arrays

4

o Mixed technologies digital, signal and power, low and high voltage) to develop advanced Smart Power ICs

o System know-how enabling the design of dedicated Smart Power ICs for complex applications

Source: iSuppli, ST

(\*) Power Management includes: Voltage Regulator/Reference, Industrial & Other Analog ASSP, Power Transistor, Bipolar PT, FET PT, IGBT, Thyristor, Rectifier & Power Diodes

Power Management Today

Key Areas of Strength

- o High voltage power MOSFETs
- o Ballast driver ICs
- o Ultrafast diodes
- o Application specific ICs

Consolidated

IMS Key Areas

SMPS

Lighting

(highfrequency

ballast)

Motor

Control

- o Analog drivers
- o High voltage power MOSFETs
- o Rectifiers
- o VIPers
- o Microcontrollers
- o Driver ICs
- o Power transistors
- o ACS switches

5

Mobile

(including

battery

charger)

Motherboard

&

Set-Top-Box

- o IPADs
- o OLED controllers
- o VIPers
- o Multi-output DC-DC converters
- o Voltage regulators



Post Kyoto  
protocols on  
reducing  
greenhouse  
gas emissions

Vision and Awareness

Energy

demand is  
increasing  
drastically

Population

and

building

density

increase g

Moving forward in Eco Sustainability...

- o Reducing power consumption through system efficiency
- o Reducing oil combustion and pollution through renewable energies and hybrid electric vehicles

f btt d b d lif

A Global Commitment

6

.... for a better day-by-day life

- o Building automation, surveillance & safety through sensor networks and remote monitoring
- o Intelligent use of energy through smart systems
- o Home healthcare through portable devices

Leveraging Smart Power ICs & Power Discretes  
Higher efficiency  
through smart  
power ICs  
Power management ICs, off-line converter ICs, integrated  
PoE ICs, mixed digital/signal/power ICs  
Power  
Transistor 1995  
PowerMESH SuperMESH MDmesh(TM) II  
-20%  
today  
-82% -90%  
2000 2005  
MDmesh(TM) V Cutting power  
losses through  
power discrete  
technology  
Power transistors and rectifiers  
Source: iSuppli  
8

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Innovation in Technologies &  
Products

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Innovation in Technologies &  
Products

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Innovation in Power Technologies

Ultra-low power 3D heterogeneous Advanced BCD, BCD-SOI  
integration/ TSV

New materials:

SiC & GaN  
technologies

Harvesting and thin

Innovative wire bonding

10

Advanced packaging &  
system-in-package

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Innovation in Power Technologies  
60um wafers for advanced IGBT devices  
Ultra-Thin Wafers  
become flexible  
90V G N RF P  
11  
GaN Power  
Transistors  
Wafers for GaN devices become  
transparent

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Innovation in Power Technologies  
New smart power  
systems  
integrating  
Microcontroller  
+ Software  
g g  
ST current and  
future technologies  
Power Section (MDmesh V)  
12  
Application Specific  
Integrated Modules  
Controller (BCD8)

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A Wave of New Products  
IPAD(TM) (Integrated Passive  
& Active Devices) solution

Ultra-small and energy-saving  
Monolithic active matrix  
OLED display power supply  
New HV power MOSFET family

intelligent power switch  
13

Advanced battery chargers  
and gas gauge monitoring

featuring worldwide best RDSon



System Innovation

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SmartGrid

The Heart of Energy Management

Home automation

and distributed power

generation

Renewable energy

Factory automation

15

SmartGrid: Power conversion and connectivity for an intelligent use of energy

Building

Power plant automation

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Power Conversion in SmartGrid

ST offers complete solutions from low-power applications to high-power energy conversion

Medium-Power

High-Power

With

- o SiC / GaN transistors
- o HV switches
- o VIPer plus
- o DC-DC modules

Low-Power

- o Low-power technologies
- o Battery power management
- o Energy harvesting
- o Power switches
- o Power transistors
- o Power management ICs
- o Mixed signal ICs

16

Source: Semicast (including Power Energy and Transportation)

Energy 2013 TAM: \$5B

CAGR 2010-2013: 7%

Smart Power Solutions

LED Street Lighting Control

Energy saving:

dimming based on available natural light

Comfort:

color changing (cool/warm) based on location  
and time of day

Driver ICs

Key Products

Architectural/fashion:

creating different effects using the same lights

Lighting control:

for specific applications like theater, stage lighting

17

Source: Semicast

Power transistors

Power factor ICs Lighting 2010 TAM: \$1B

CAGR 2010-2015: 9%

Smart Power Solutions

Smart Meters

Gas Meter

Electronic flow meter

Energy Meter

Motor control ICs

Key Products

Concentrator

provides info to the consumer on  
energy and gas usages

18

Source: ABI Research

Power line modems

Energy meter ICs

Smart Electricity Meters

TAM 2009: 76M units

CAGR 2010-2013: ~18%

Smart Power Solutions  
Hybrid and Electric Vehicles  
Plug-in battery charger for HEV  
Combine an electric motor and an internal combustion engine  
Reduce air pollution from greenhouse gases  
Operating cost equivalence: 20 (cent)US / liter\*\*  
Power transistors  
Key Products  
19  
More than \$600 of  
semiconductors  
for every HEV (\*)  
Source: (\*) Strategic Analytics, (\*\*) US Dept of Energy  
Driver ICs  
32-bit microcontrollers

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Smart Power Solutions

Photovoltaic

ST Solution:

One microinverter

module per panel

vae Maximizing energy output (MPPT)

vae Energy monitoring (daily, monthly, yearly, etc.)

vae Diagnostic, anti-theft and anti-tearing protection

vae Reducing operation costs due to modularity

Remote

Monitoring &

PV Panel Control

Cool bypass switch

Key Products

20

Power transistors

MPPT

(Max Power Point Tracker)

Electronics on panel value from \$1.50 to \$15

PV energy production growth

O(( 2010 a(3) about 7 GW

(about 35 million single photovoltaic panels)

O(( 2020 a(3) about 56 GW

Source: European Photovoltaic Industry Association, ST

Smart Power Solutions  
Photovoltaic  
Value  
Smart Power System  
MPPT  
Max Power Point Tracker  
DC/DC  
Converter  
DC/AC  
Inverter MOSFET  
SiC  
MPPT  
Max Power Point Tracker Cool Bypass Switch  
Cool Bypass Switch  
Cool Bypass Switch  
Microinverte  
21  
Complexity  
PLM  
Power Line Modem  
System Monitoring  
(Energy Level, Faults, etc.)  
DC/DC  
Converter  
DC/AC  
Inverter  
MPPT  
Max Power Point Tracker  
DC/DC  
Converter Bypass Diode

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Smart Power Solutions  
Home Healthcare  
Insulin  
Flexible Lens for  
Eye Pressure  
Monitoring  
Electro  
Cardiogram  
Portable distributed  
diagnostics  
and remote monitoring  
Battery management  
IC  
Key Products Movement  
Recognition  
Nano Pump Temperature  
Sensor  
Pressure  
Sensor  
22  
Portable Healthcare  
2010 TAM: \$1B  
CAGR 2010-2015: 11%  
Source: Semicast  
ICs  
8-bit low-power  
microcontrollers  
IPAD and protection  
Step Counter

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Smart Power Solutions  
Energy Harvesting  
Integrating harvesting  
in smart systems  
Solar  
Electro- Thermal  
chemical Enabling wireless sensors  
for energy autonomy  
Autonomous wireless sensor node  
Harvesting  
Device (PV,  
Piezo, etc) Low Power  
RF  
Transceiver  
Sensors  
Ultra Low  
Power  
Microcontroller  
Energy  
Conversion  
Battery Storage  
Wind  
RF  
Kinetic  
Energy  
23  
The Future is  
Here STMicroelectronics and Micropelt  
demonstrate 'Perpetual Energy'  
thermoharvesting power supply

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A "Virtuous" Circle  
Smart Power ICs Develop Solutions  
System Approach  
Acts as a  
Flywheel  
24  
Product Innovation  
Customer Endorsement

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TRANSFORMING THE PORTFOLIO

May 2010 1 Date: 2010-05-07 COMPANY CONFIDENTIAL

Pascal Langlois

Senior Vice President, Chief Sales and Marketing Officer

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TRANSFORMING THE PORTFOLIO

E & f h o High-value entry

- o Smartphones
- o Connected devices
- o Application engine
- o Modem
- o Connectivity
- o Diversified customer portfolio
- o Open/complete platforms
- o Entry feature phones
- o Modem only
- o Three big customers
- o Custom solutions

2

p p p

- o Europe and Asia o Global

MARKET TRANSFORMATION

Thin

Modems Platforms

In Production

HSPA

EDGE

TD

M340

HSDPA

5209

EDGE

M6718

TD HSPA

DRIVING MOBILE BROADBAND

EVERYWHERE

Mobile Broadband and M2M Devices

Entry

& Feature Internet and Multimedia enabled solutions

Separated Smartphone solutions

(Application engine + Thin

modem)

TD-U67XX

WCDMA

U6715

HSDPA

THE BEST SMARTPHONE PLATFORMS

FOR ALL TIERS

High-end and mid range smart devices

Platforms Single-chip 2G & EDGE

U33x

HSPA/HSDPA

T72XX

TD-HSDPA

Connectivity and

Enhancements

STLC4560 Complete Platforms

WLAN

GNS7560

GPS

STw5200

Audio

STw8019

TVout

STLC2690

BT/FM

65XX

EDGE

ADDING VALUE

TO AFFORDABLE DEVICES

High value entry devices

3



TODAY 2G/EDGE  
UMTS/  
HSPA  
TD-]SCDMA  
Thin  
Modems  
Platforms HSPA  
EDGE  
TD  
M340  
HSDPA  
5209  
M6718  
TD In Production  
Entry  
& Feature Internet and Multimedia  
bl d l i  
Separated Smartphone  
solutions (Application engine  
+ Thin modem)  
EDGE  
TD-HSPA  
U67XX  
WCDMA  
U6715  
HSDPA  
Platforms enabled solutions  
Single-chip 2G & EDGE  
U33x  
HSPA/HSDPA  
T72XX  
TD-HSDPA  
Connectivity and  
Enhancements  
STLC4560 Complete Platforms

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TOMORROW  
Thin  
Modems  
Platforms  
In Production Announced  
LTE / HSPA+ Mobility  
Best combined UL/DL  
performance  
Data in every region  
M720  
LTE/HSPA+  
M340  
HSDPA  
5209  
EDGE  
M570  
HSPA+  
M700  
LTE  
M6718  
TD-HSPA  
UMTS/ 2G/EDGE  
HSPA  
LTE TD-]SCDMA  
Entry  
Platforms  
Application  
Processor with  
Integrated  
Modem  
Platforms  
Internet and Multimedia  
enabled solutions  
High-performance  
Smartphone platforms  
U8500  
HSPA+  
U68XX  
HSDPA  
U67XX  
WCDMA  
U6715  
HSDPA  
U5500  
HSPA+  
TD  
5  
Connectivity and  
Enhancements  
CW1200 Complete Platforms  
WLAN  
CG2900  
BGF  
AV5230  
Audio PTE  
AV8100  
HD TVout  
Single-chip 2G & EDGE

U33x  
HSPA/HSDPA  
T72XX  
TD-HSDPA  
E4908  
EDGE  
G4850/52  
GSM/GPRS  
E4910  
EDGE  
T6718  
TD-HSPA  
June 3, 2010

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A COMPLETE SINGLE CHIP 2G PORTFOLIO

Single Chip

ULC+ GSM/GPRS

MPEG4, MP3, FM record

Dual SIM / Dual Standby

Single-Chip EDGE

WQVGA display, touchscreen

3MP camera

MPEG4 H.263 MP3 AAC+

Single-Chip EDGE-Rx

QVGA display, 2MPix camera

MPEG4, H.263, MP3, AAC+

USB FS

Single Chip

ULC GSM/SMS

MP3 ringtones

Dual SIM / Dual Standby

MPEG4, H.263, MP3, G4852 E4910

Bringing high value features to the entry segment

G4850 E4908

6

CONNECTIVITY AND ENHANCEMENTS

Bluetooth

Fully-integrated single-chip Bluetooth

GPS

Leading footprint and power

BT/FM/GPS

First 45nm Combo

L d i f t i t i

CG2900

WLAN

Outperforms in Bluetooth co-existence

FM Radio

Over 1 Billion FM radio shipped

Video

Full HD TV out

Audio

Extend playtime without reducing quality

Leading footprint size

802.11a/b/g/n

( 50mm2 BOM

Integrated FEM, SMPS

CW1200

HDMI/CVBS combo

Full HD 1080p

7.1 audio surround

AV8100

AV5230

102 dB SNR

Integrated headset AMP

Power

Smart power distribution

Playback Time Extender

Integrated into complete platform solutions

7

U6715 SMARTPHONE FOR ALL  
HSDPA supporting multiple OS  
Touch screen  
U6715  
5 Mpixel camera  
QVGA or WQVGA Video  
3G talk time up to 7 hours  
standby up to 25 days  
Android ready  
Great user experience at an affordable price  
8

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INNOVATION FOR SMARTPHONES

Dual core architecture with > 1Ghz

Over 5000 DMIPs power

Full HD Camcorder 1080p

20 megapixel cameras

High-end 3D graphics subsystem

Dual core architecture

HD video 720p

12 megapixel cameras

3D hi b t

o TD variants for the Chinese market

C ibili d l bili f

Integrated connectivity

HSPA+ modem

Supporting multiple OS

U8500

graphics subsystem

Integrated connectivity

HSPA+ modem

U5500

o Compatibility and scalability for our customers

o Reference hardware for ARM Mali ecosystem

o Driving evolution of SMP for Android

Technology leadership brought to mainstream

9

Feature rich TD-HSPA/EDGE platform  
Enabling affordable high-speed internet  
phones  
ADVANCED TD-SCDMA SOLUTIONS  
Thin modem platform with  
TD-HSPA for higher uplink data rates  
65nm process  
5 megapixel camera  
WQVGA display  
Improved overall integration  
T6718 M6718  
Leader in TD-SCDMA in China - 12 Million chipset shipped  
10

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MOBILE BROADBAND WITH HSPA+ AND LTE

Commercially available chipsets

HSPA+ technology

Optimized modem

solution suitable for USB data devices

best-in-class thermal performance

Full data speed downlink of 21Mbps and

uplink of 5.7Mbps simultaneously

Modem optimized for easy integration into a  
variety of devices

M570

M720

First to successfully show interoperability between HSPA and LTE

11



ADDRESSING MODEM EVOLUTION

Challenges

Increasing air  
interfaces

Then Now

TD

LTE

HSPA+

New ST-Ericsson

ltd

- o Software-defined radio access

- o LTE 100Mbps, HSPA+ 42Mbps

- o Target >2X power

improvement

- o Scalable for cost

management

2G

2G/3G

EDGE multi-mode modem

architecture

Increasing

adoption of

connectivity

BT

FM

BT

GPS

WIFI

- o Co-existence built-in

- o Combos & platform

integration

Increasing

adoption of

connectivity

12

- o Building on existing LTE

solution

- o Single SW and HW platform

- o Drastic reduction of testing

needs

Size & cost

June 3, 2010

SUMMARY

o oppoTrrtaunnsiftoiersming the portfolio to address key market  
Complete portfolio with highly competitive products  
Good feedback from customers on the new portfolio

13

DEMOS  
Thin  
Modems  
Platforms M570  
Entry  
Application  
Processor with  
Integrated  
Modem Platforms  
U8500 + Connectivity  
(CG2900 & CW1200)  
Y  
Platforms  
14

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SIGNATURES

Pursuant to the requirements of the Securities Exchange Act of 1934, STMicroelectronics N.V. has duly caused this report to be signed on its behalf by the undersigned, thereunto duly authorized.

STMicroelectronics N.V.

Date: June 4, 2010

By: /s/ Carlo Ferro

Name: Carlo Ferro

Title: Executive Vice President and  
Chief Financial Officer